



# catalog

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## INTEL Chief River Platform

**Version : A**  
**Drawing by : Wain**

### Notes:

Part Value Prefix : "@" means nopop

Net Value suffix : "#" means Low Active

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<b>Title</b> <Title>		<b>Size</b>	<b>Sheet</b>
C		Name	Cover Sheet
<b>ENGINEER:</b> golden		<b>Date:</b> Wednesday, March 05, 2014	<b>Sheet</b> 1 of 38
		<b>Rev</b>	<b>A</b>

# M300B/M300H BLOCK DIAGRAM

**System Power**  
TPS51125

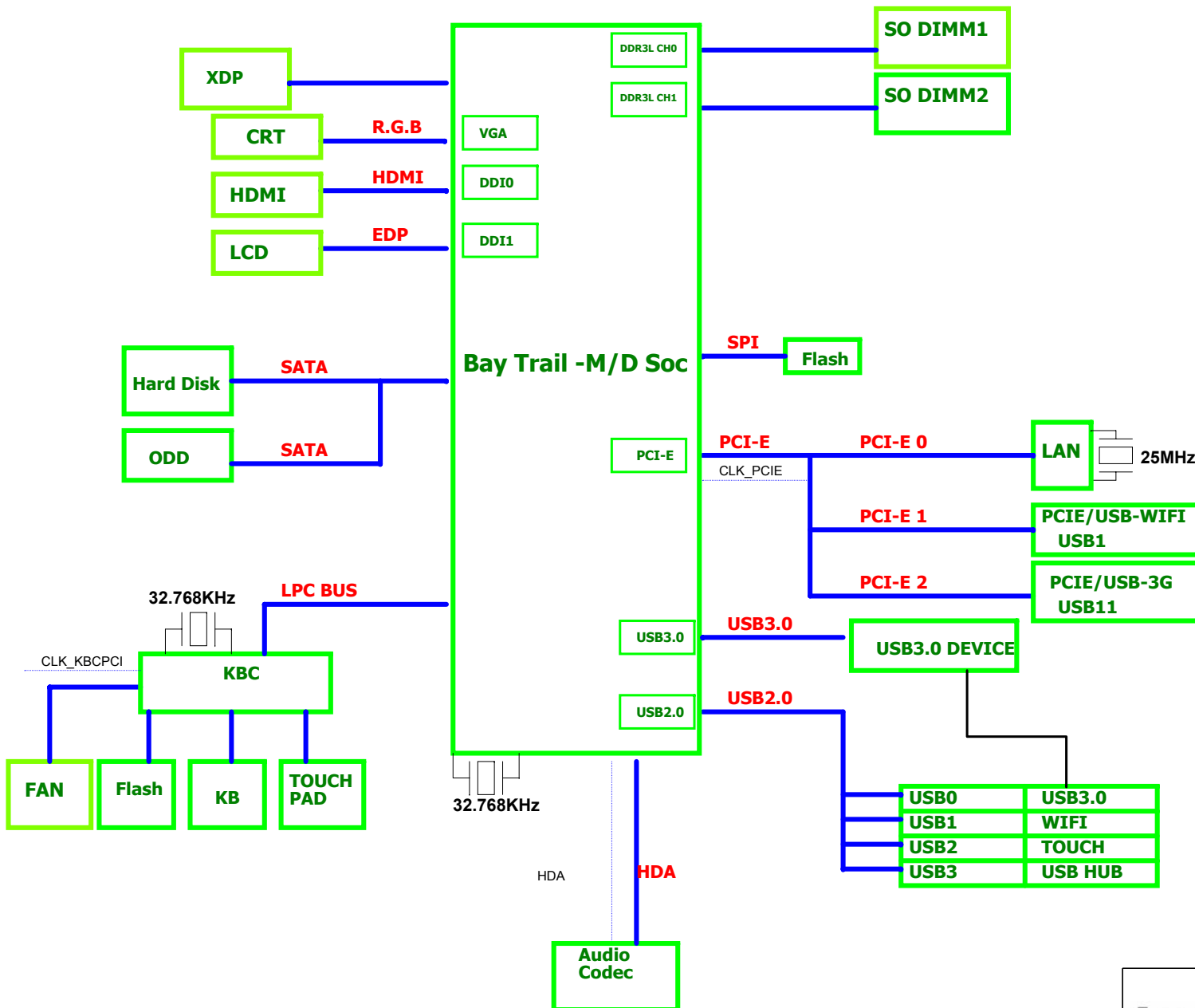
**CPU & GFX Power**  
TPS59641

**dGPU Power**  
TPS51117

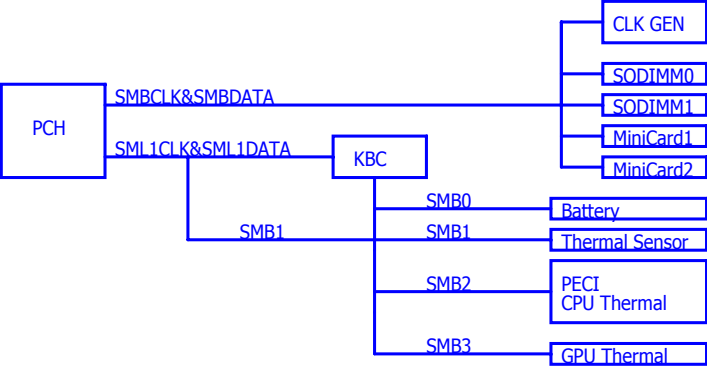
**DDR3L Power**  
TPS51216

**Charger**  
BQ24725

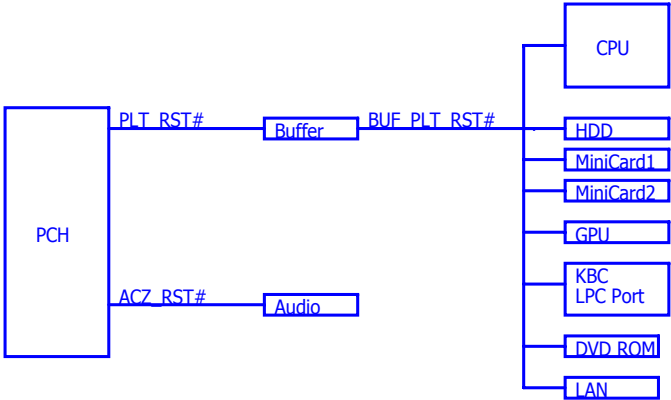
**S3/S4 Control  
and Discharge**



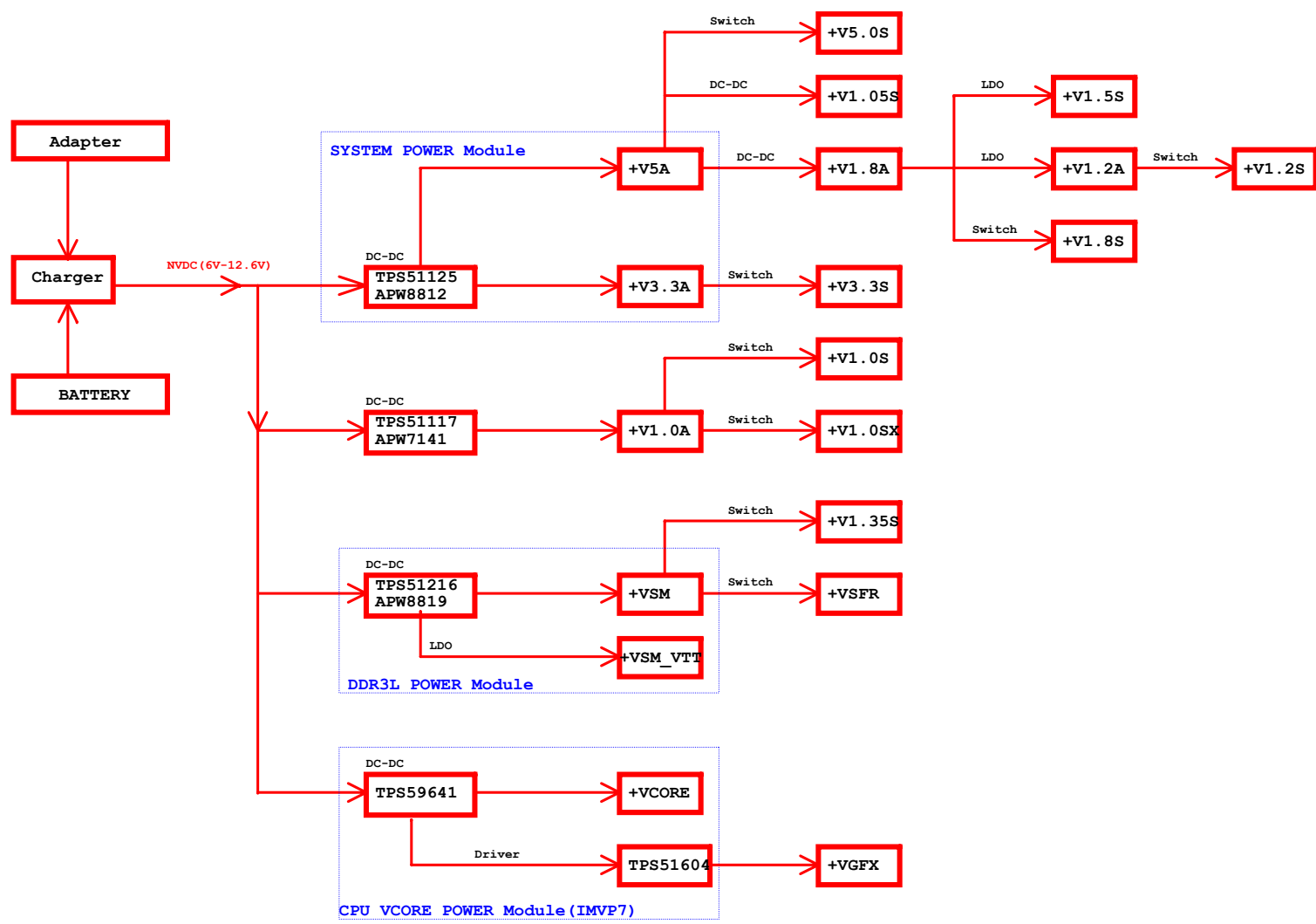
SMBUS TOPOLOGY

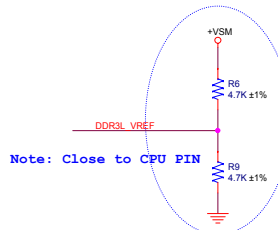
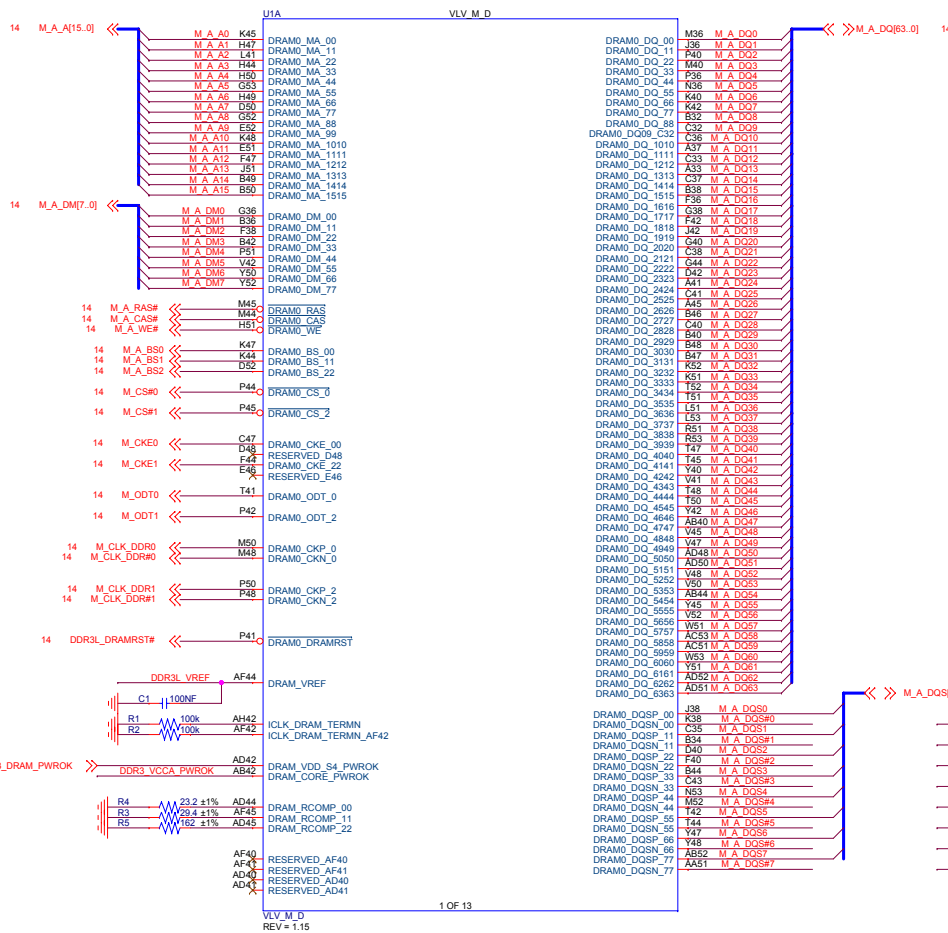


RESET TOPOLOGY

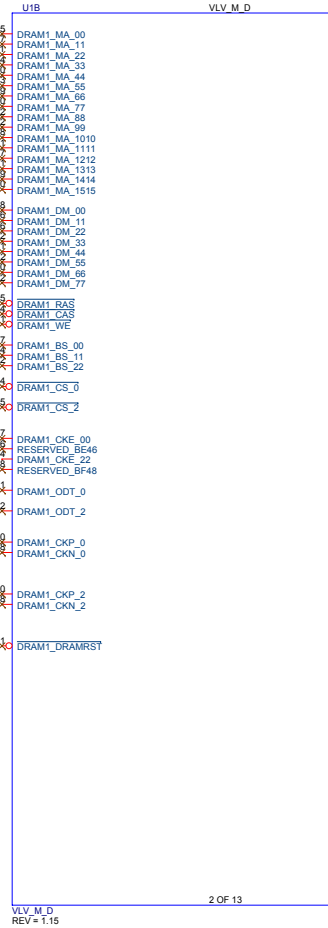
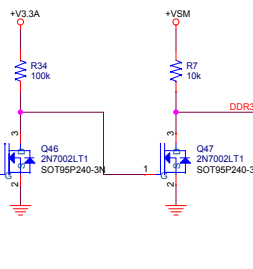


POWER Delivery Architectural Block Diagram





19 DDR3L\_VREF



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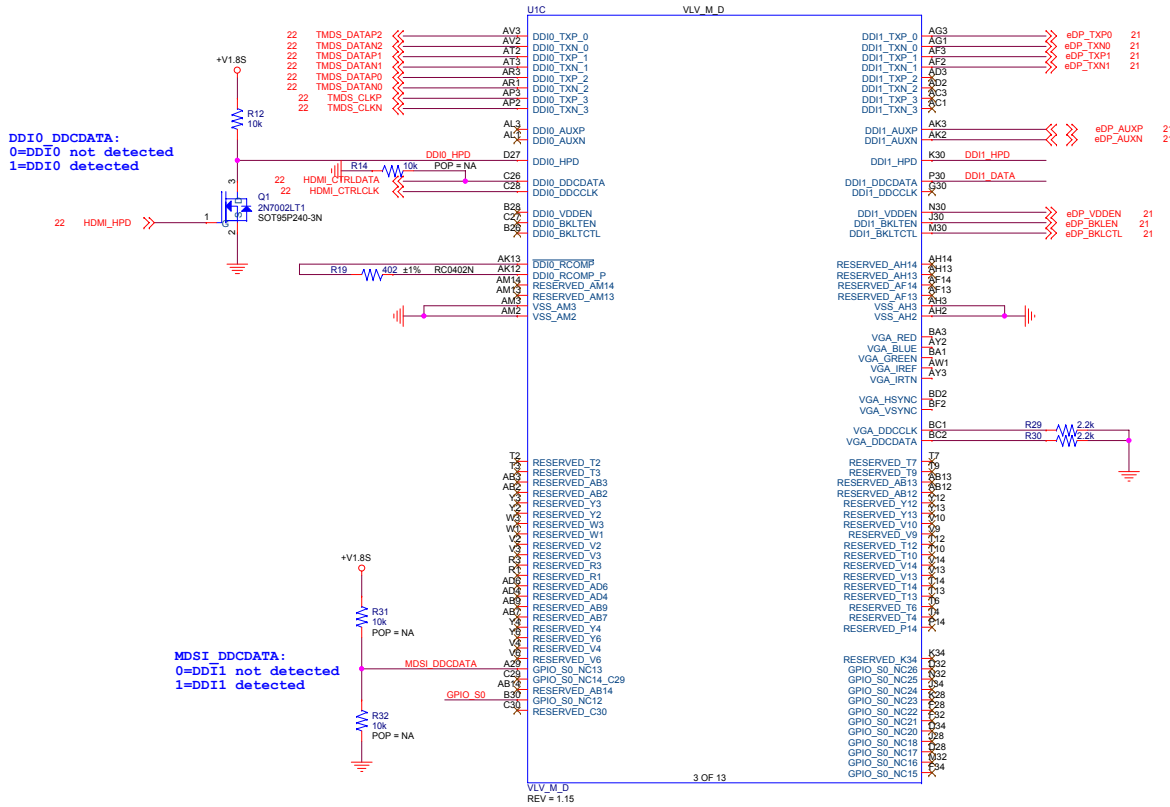
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**Title** <Title>

Size C Sheet Name SOC DDR3L A & B Rev A

Date: Wednesday, March 05, 2014 Sheet 6 of 38

ENGINEER: golden



#### CRT Disable Guidelines

Name.	System Pull-up/ Pull-down.	Schematics Notes.
VGA_RED VGA_GREEN VGA_BLUE VGA_HSYN VGA_VSYN VGA_IRTN VGA_IREF		Leave as No Connect.
VGA_DDCCLK VGA_DDCDATA	Pull down to GND.	

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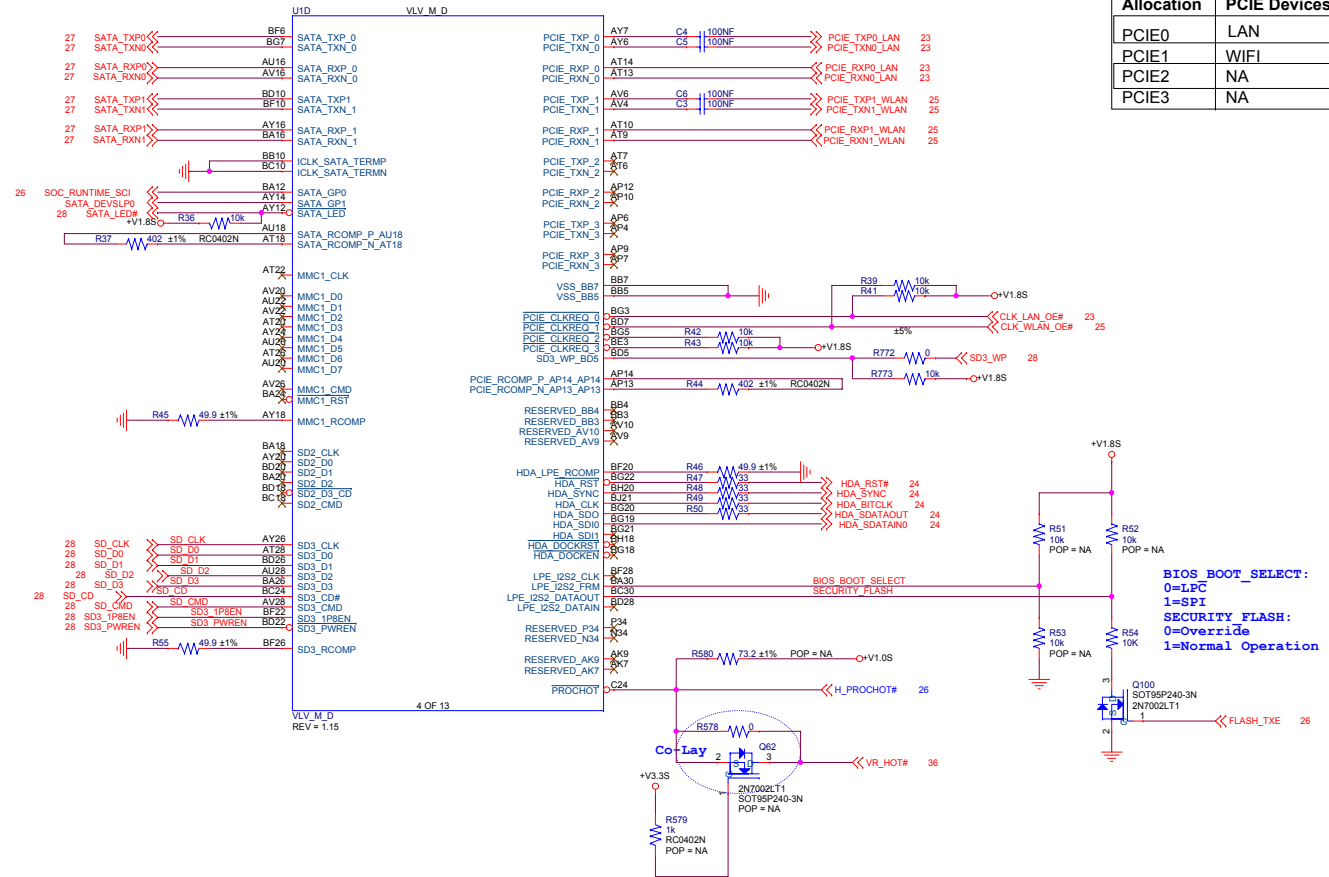
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Title <Title>

Size C Sheet Name SOC DDIO & VGA Rev A  
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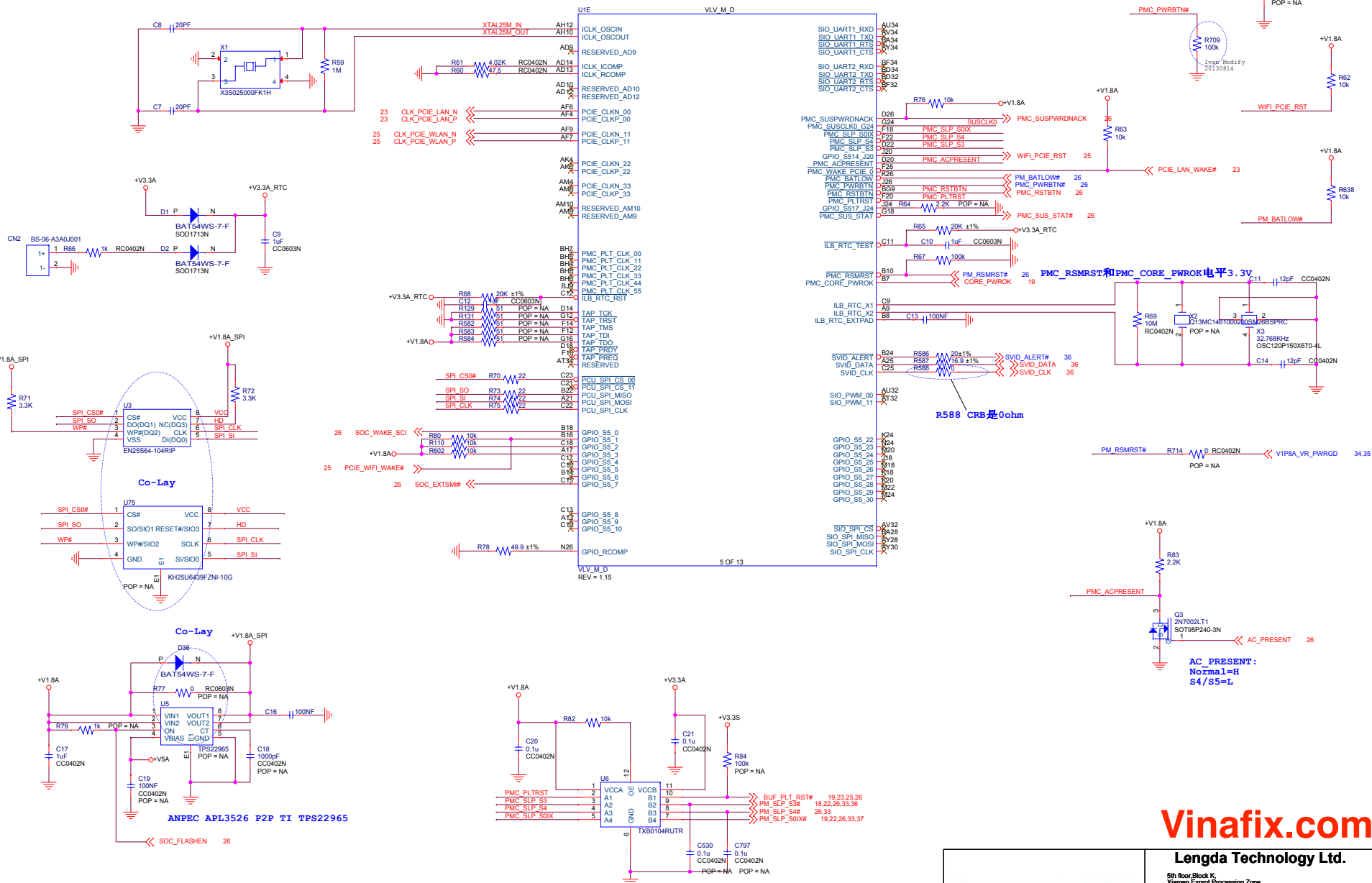
ENGINEER: golden

Allocation	SATA Devices
SATA0	ODD
SATA1	HDD



Allocation	PCIe Devices
PCIe0	LAN
PCIe1	WIFI
PCIe2	NA
PCIe3	NA





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Size Sheet SOC CLK & SPI & RTC & GPIOs

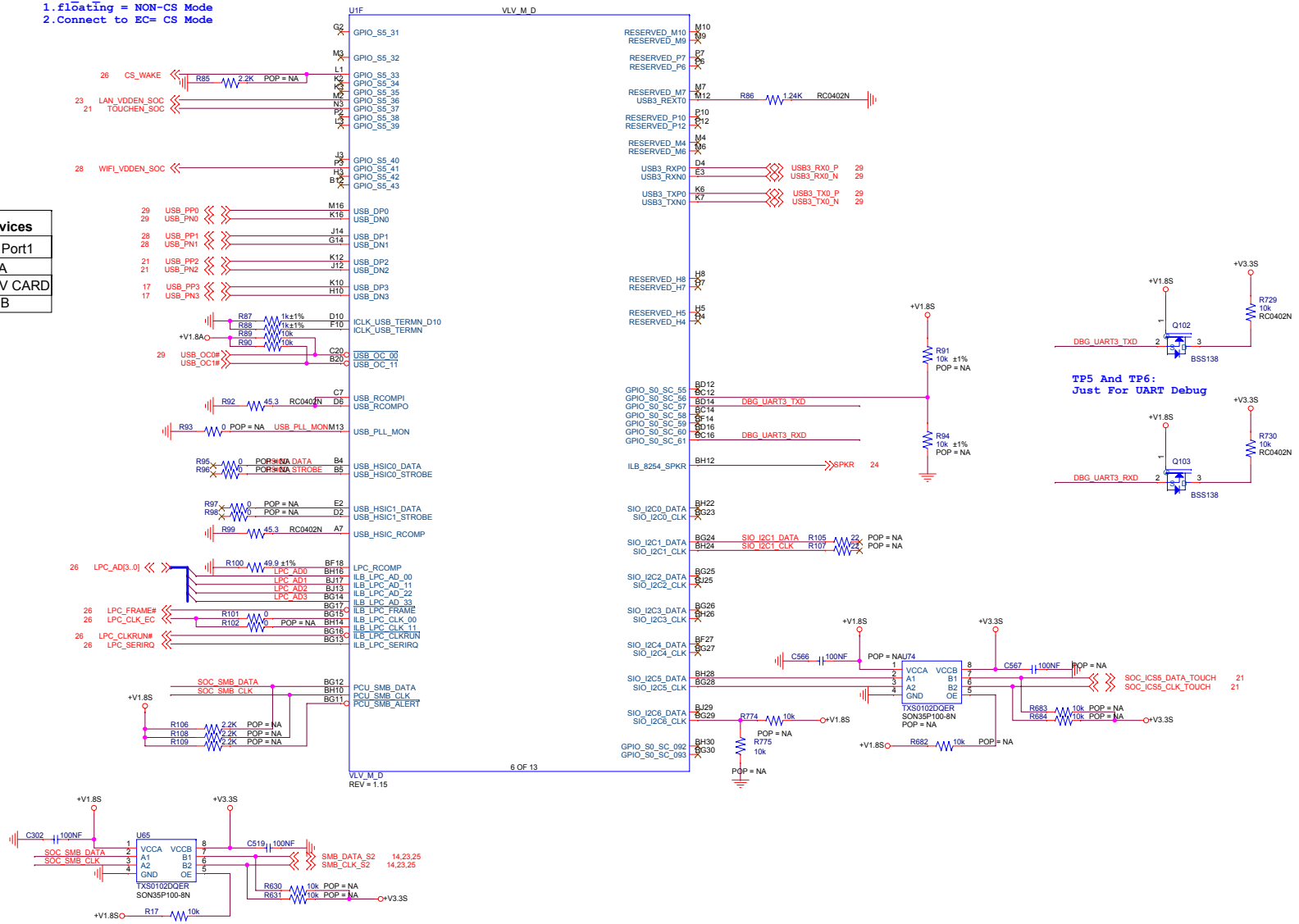
Date: Wednesday, March 05, 2014 1 Sheet 9 of 38

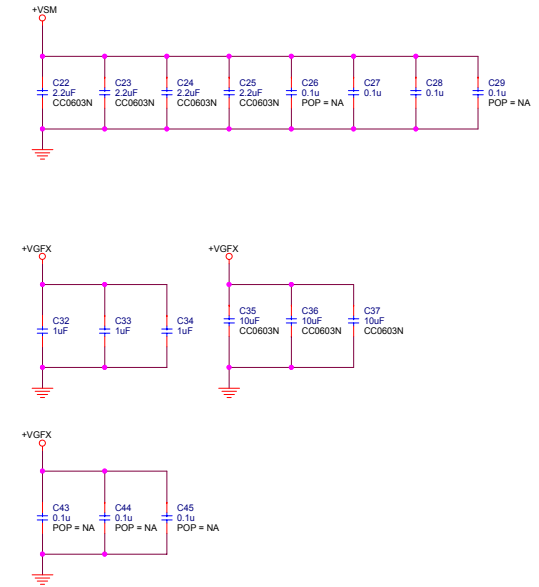
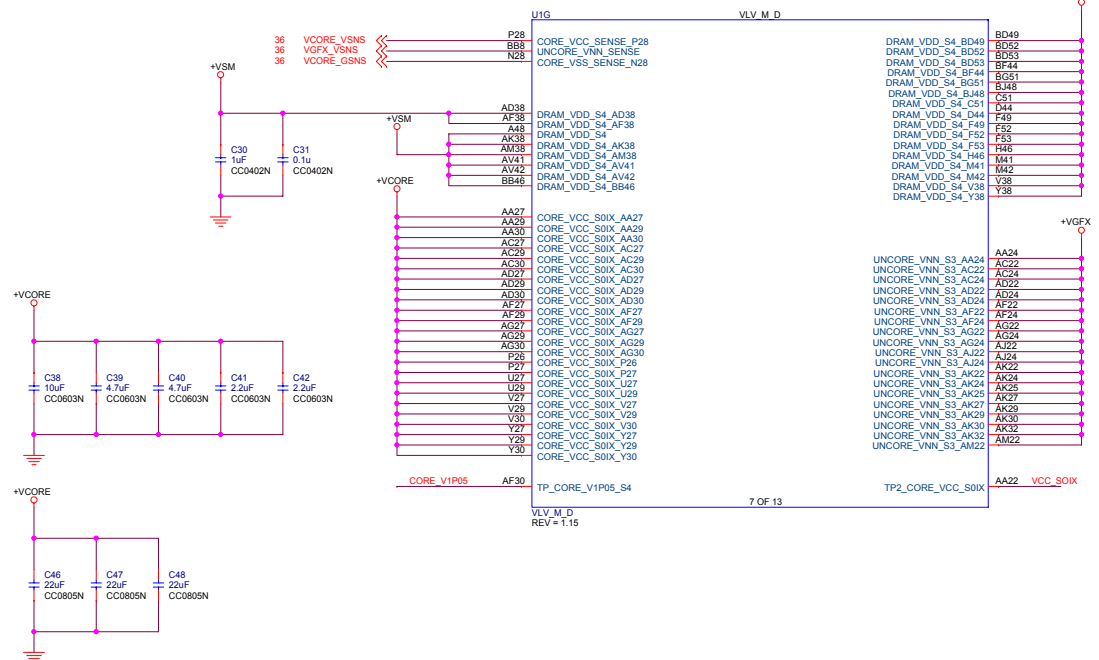
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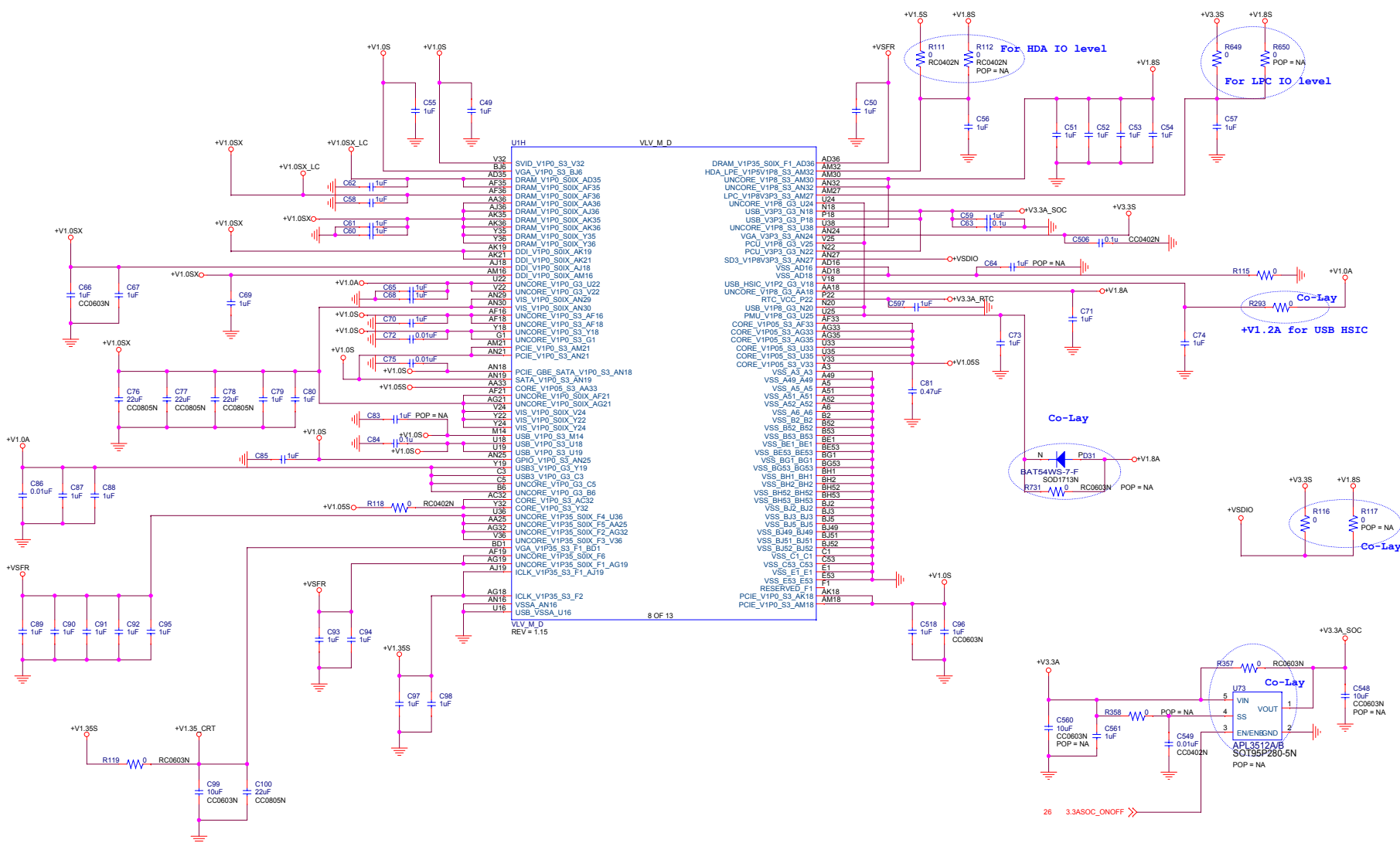
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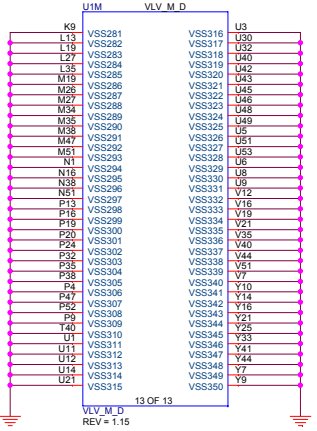
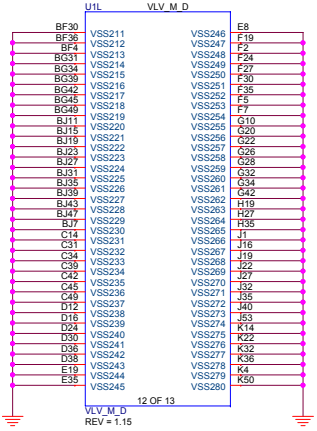
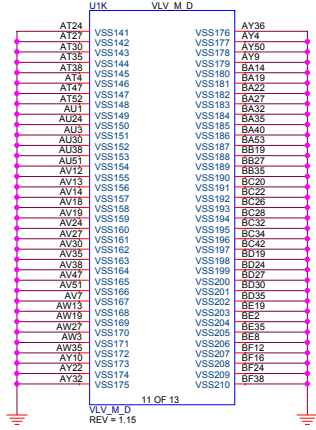
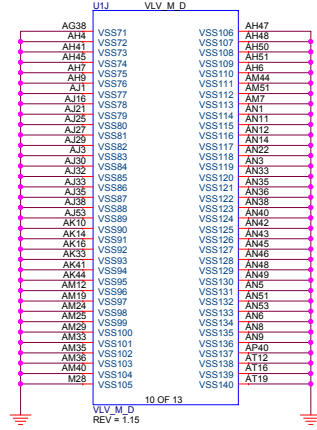
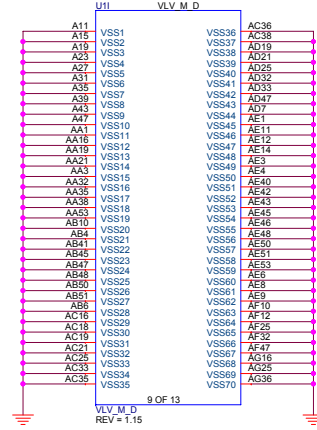
GPIO\_S5\_33:  
1.floating = NON-CS Mode  
2.Connect to EC= CS Mode

Allocation	USB Devices
USB0	USB3.0 Port1
USB1	CAMERA
USB2	Touch/TV CARD
USB3	USB HUB









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Size C Sheet Name SOC VSS Rev A

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# DDR3 SODIMM0

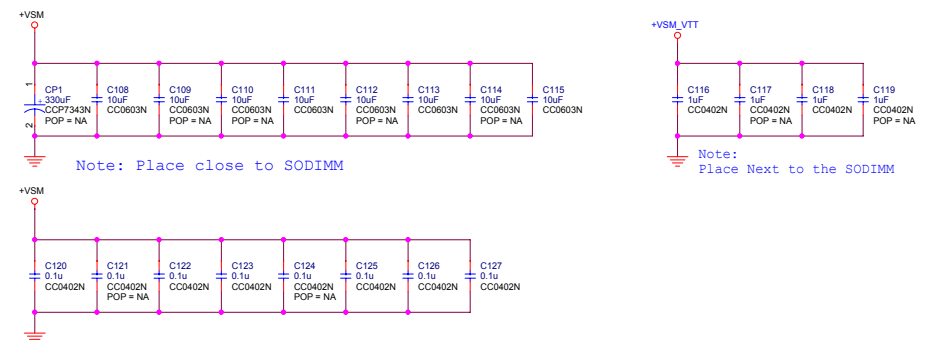
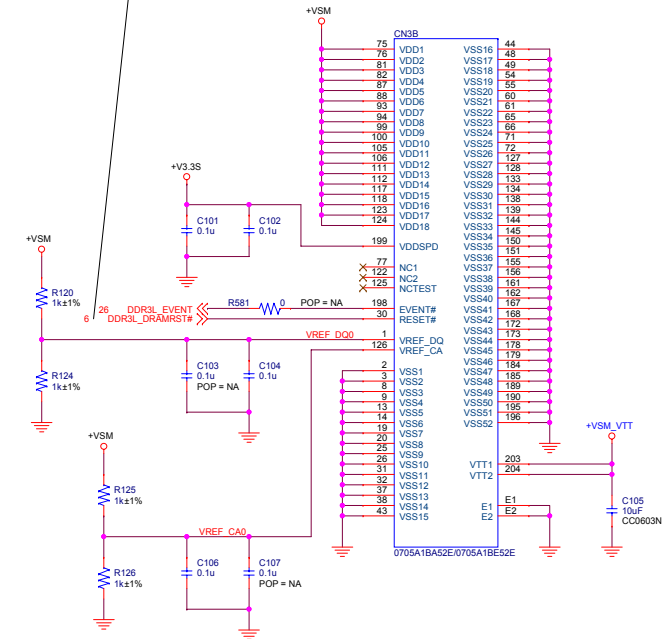
Layout Note:

Place the 0-Ω resistors close to SO-DIMM connector.

The overall routing length for both DIMM VREF traces should be  $\leq 5000$  mils (127 mm). Avoid changing reference plane during the entire routing length. If reference plane

Avoid changing reference plane during the entire routing length. If reference plane has to be changed

during the transition to 0-Ω resistors, then GND stitching vias are needed next to resistor pads. Place GND stitching vias within 100 mils (2.54 mm) of DIMM\_VREF traces close to SO-DIMM connector.



VSM VTT

C116 1uF CC0402N

C117 1uF CC0402N POP = NA

C118 1uF CC0402N

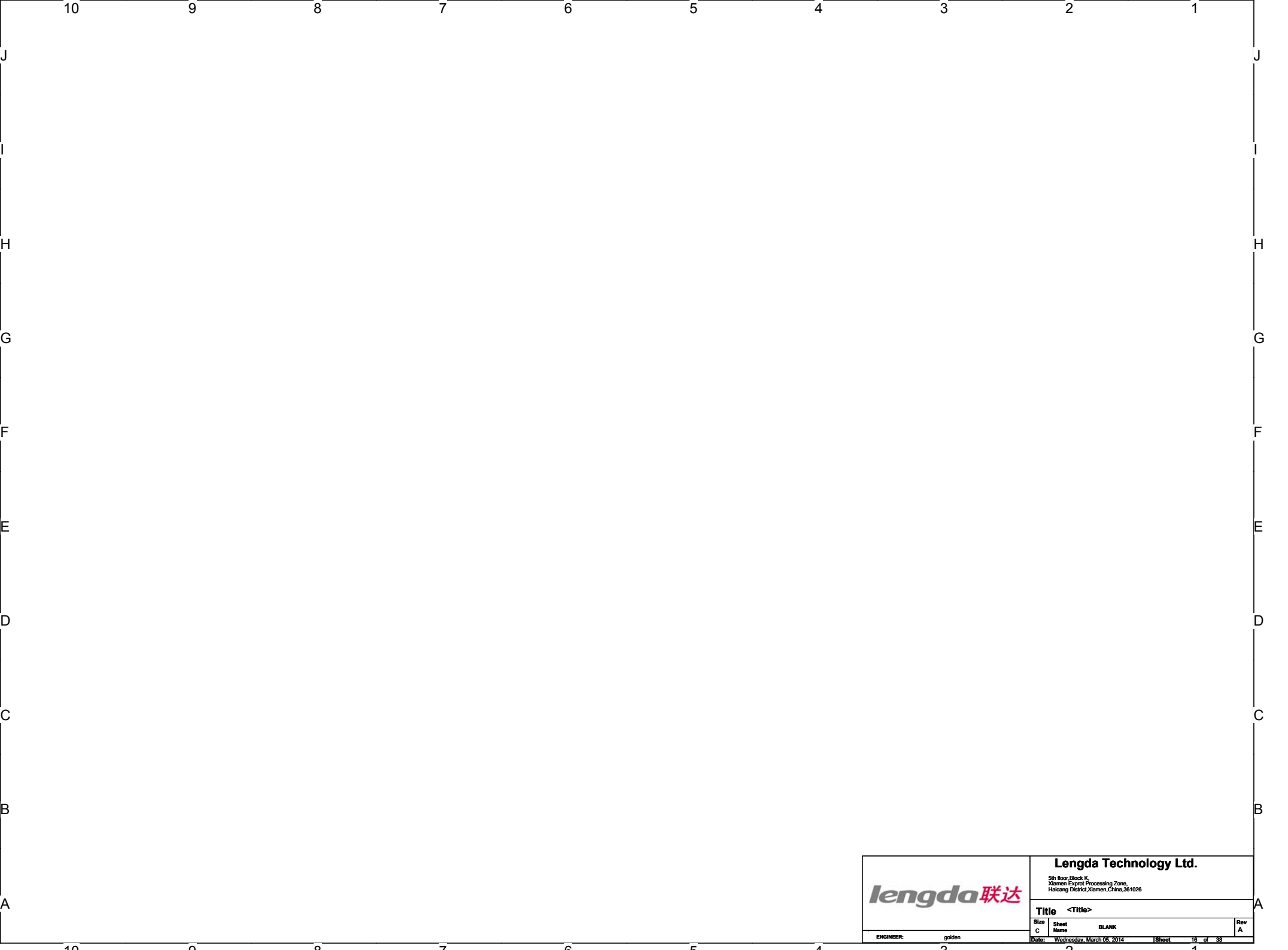
C119 1uF CC0402N POP = NA


Note:  
Place Next to the SODIMM

Note: Place close to SODIMM

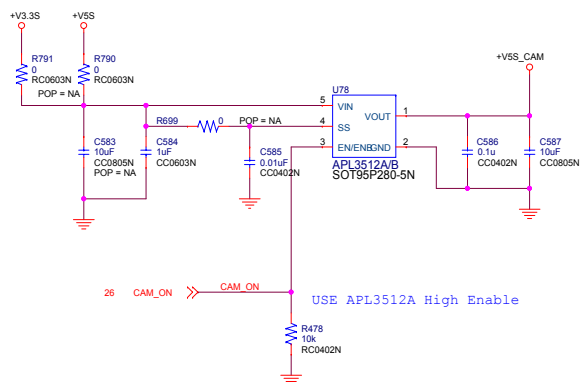
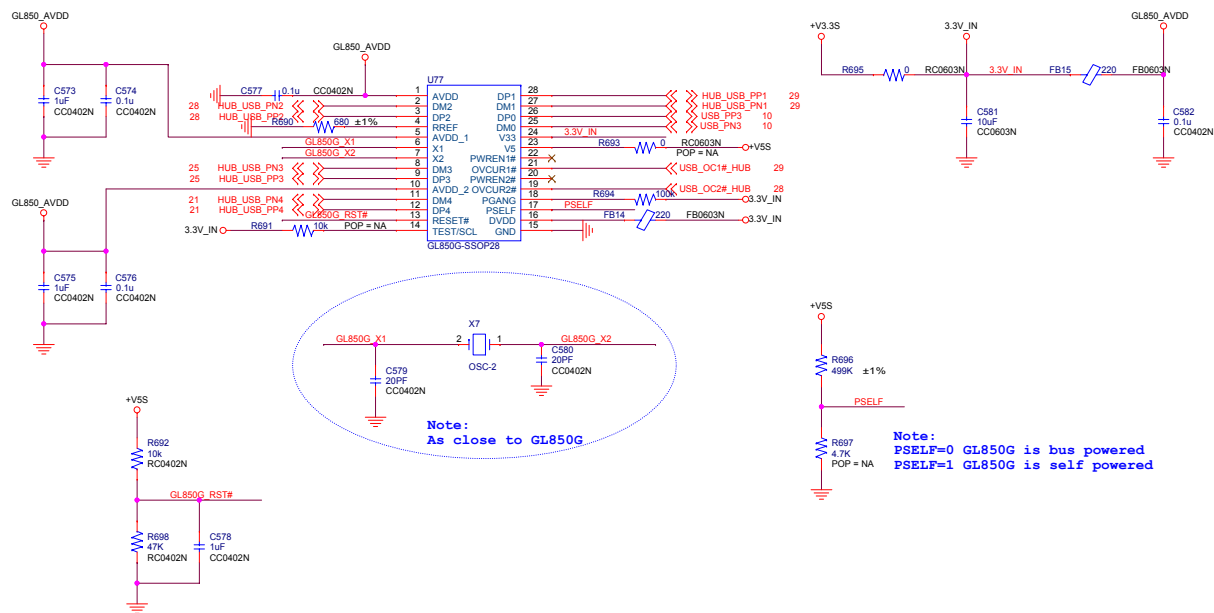
Note:  
Place Next to the SODIMM



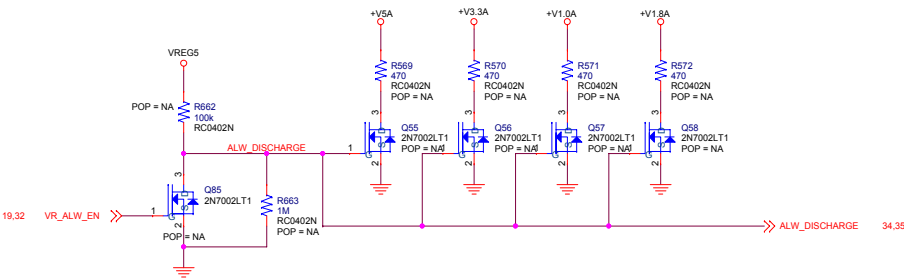
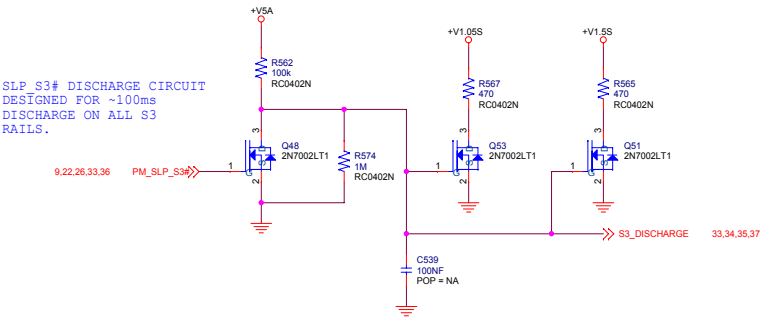


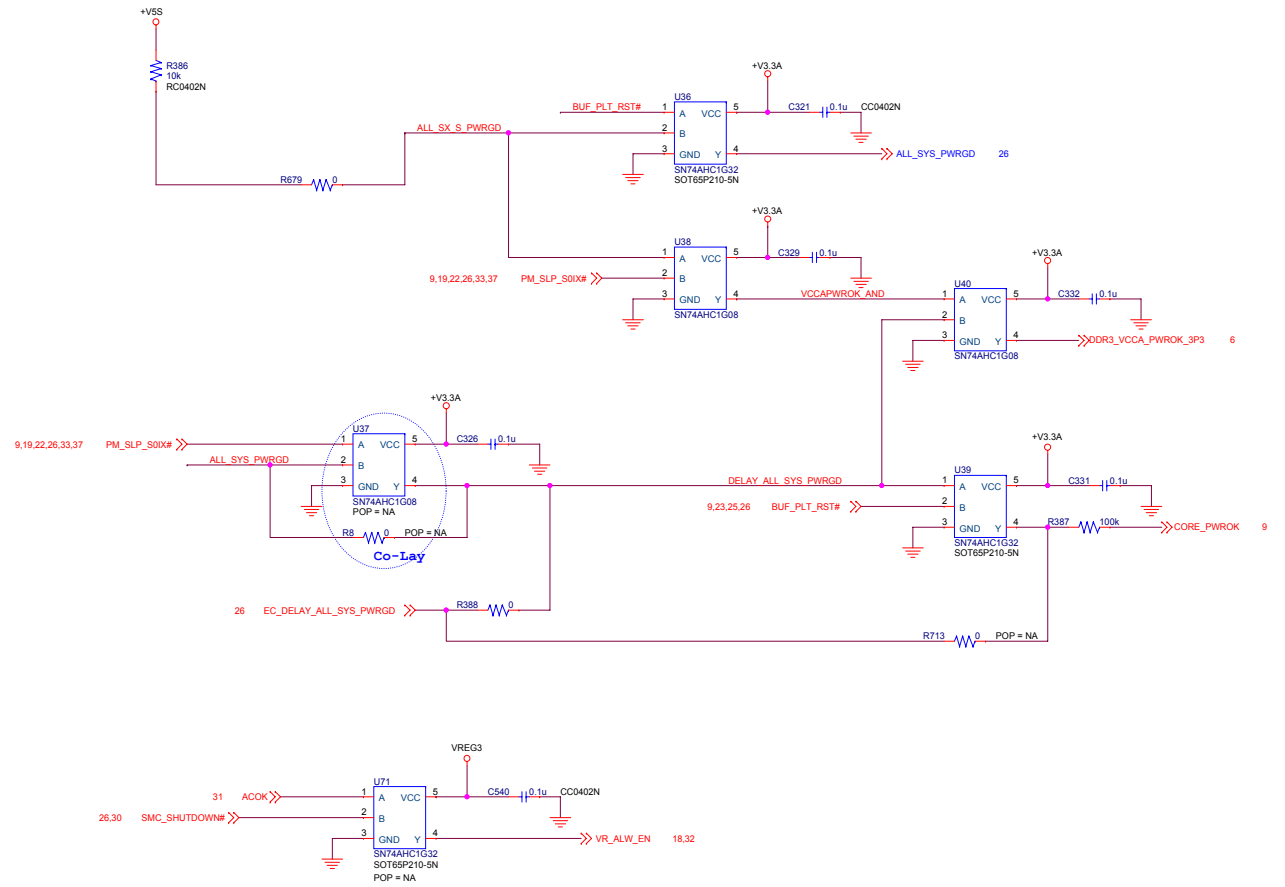
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	<b>Title</b> <Title>		
Size C	Sheet Name	BLANK	Rev A
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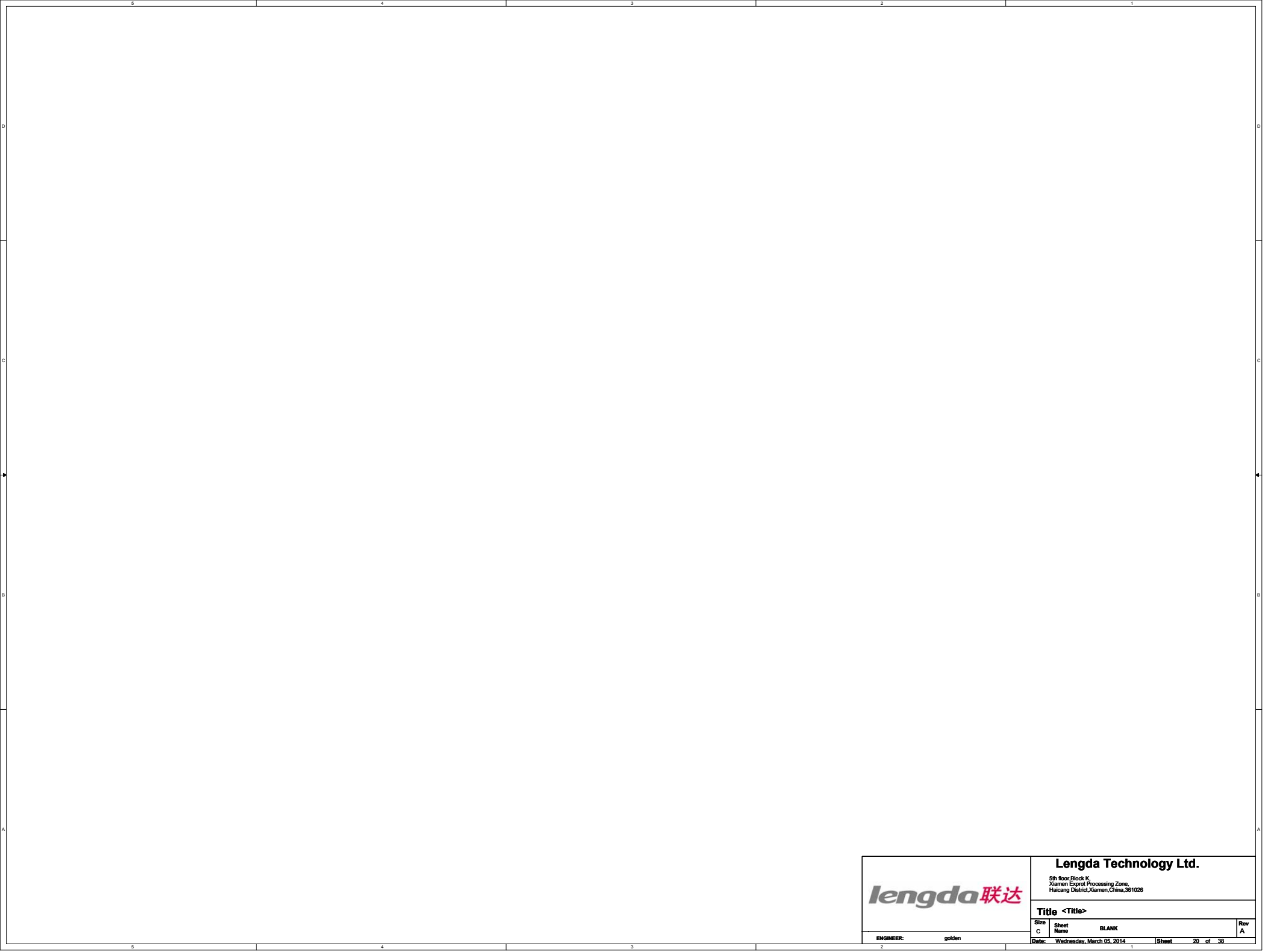





Power Discharge Circuit









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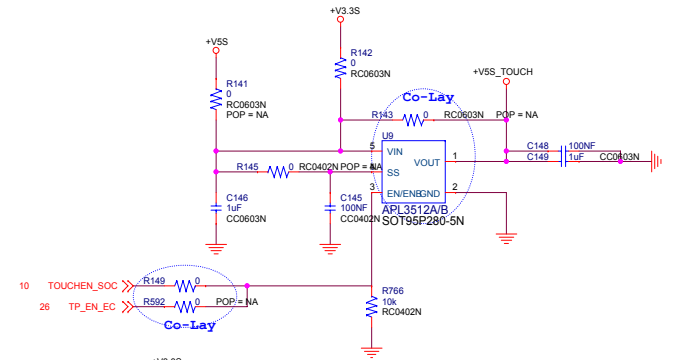
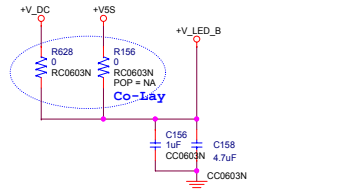
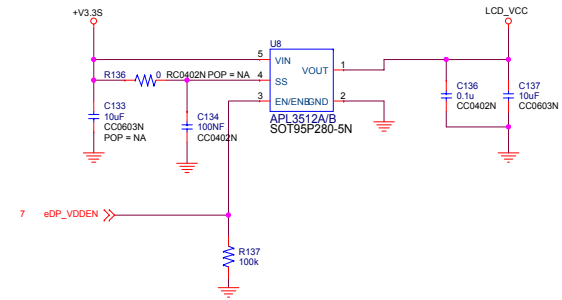
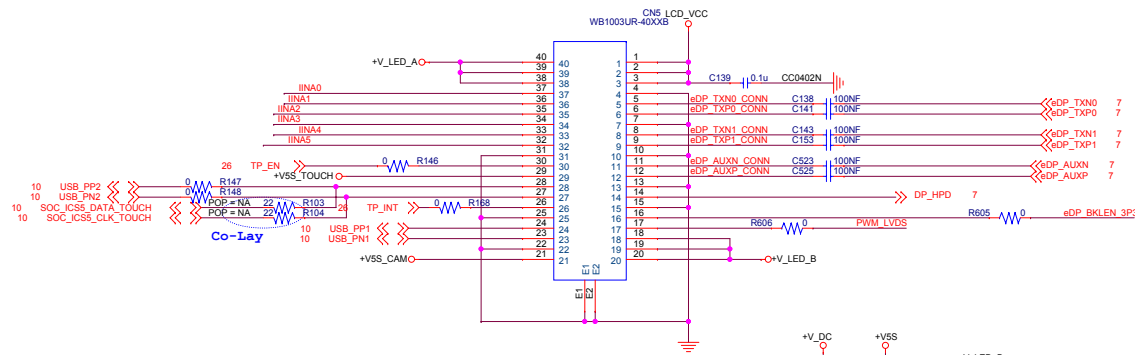
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Size	Sheet	Rev
C	NameBLANK	A

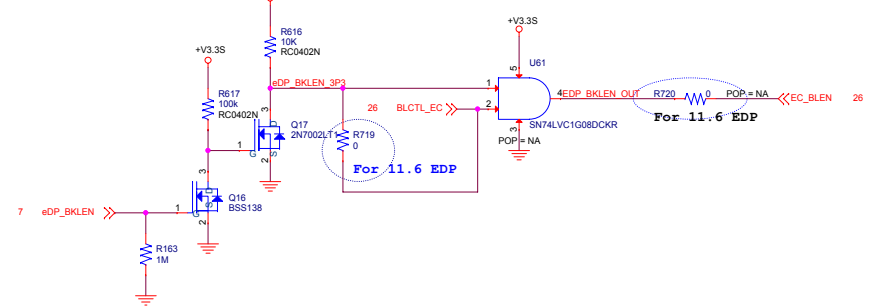
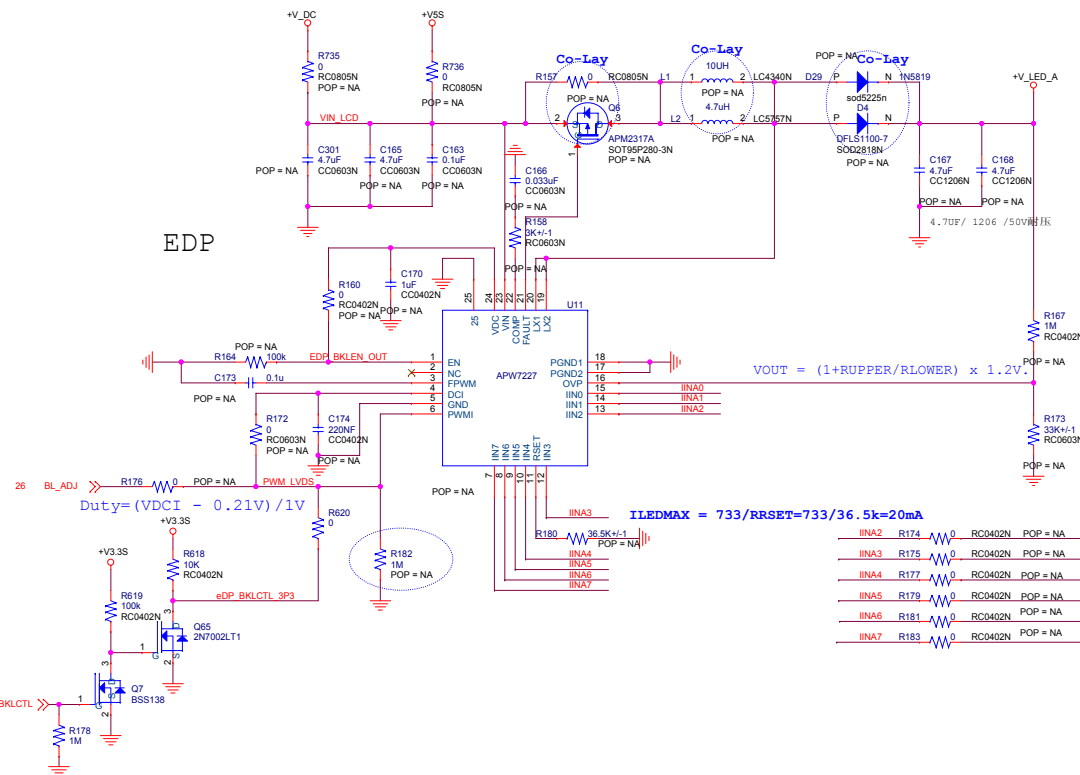
Date: Wednesday, March 05, 2014 1Sheet 20 of 38

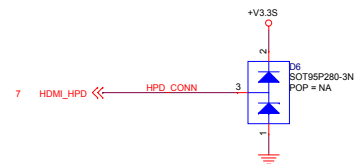
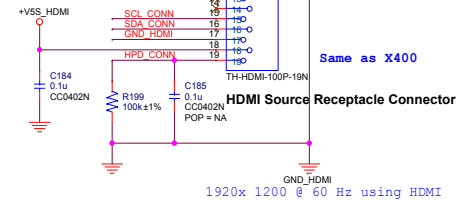
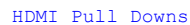
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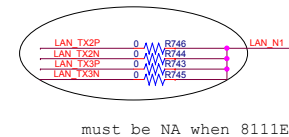
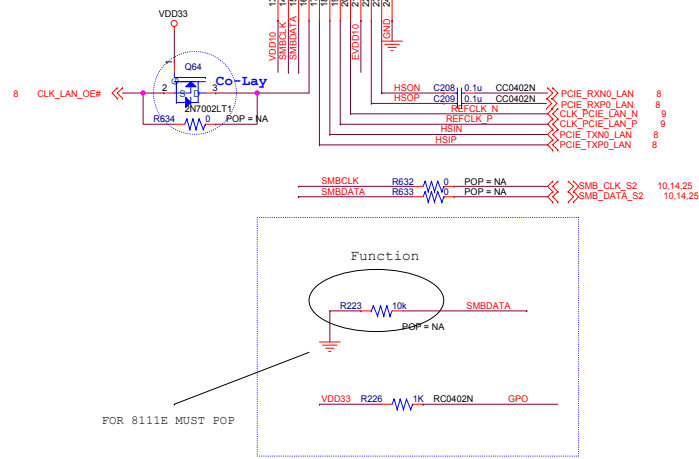
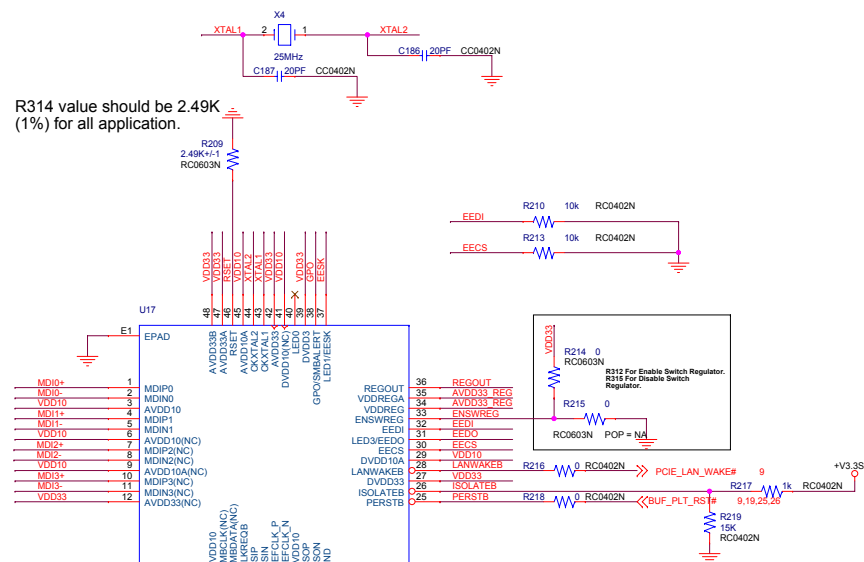
# LCD Connector



## EDP



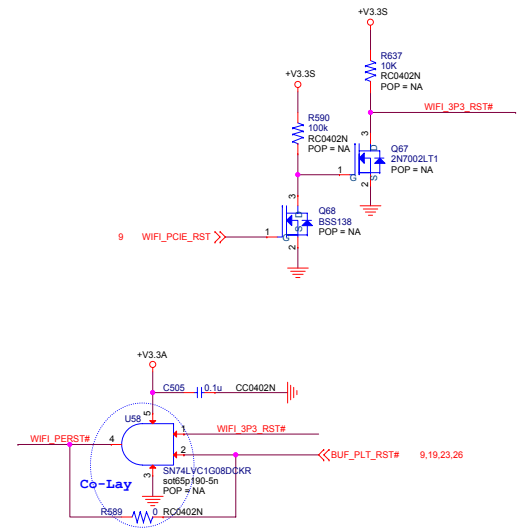
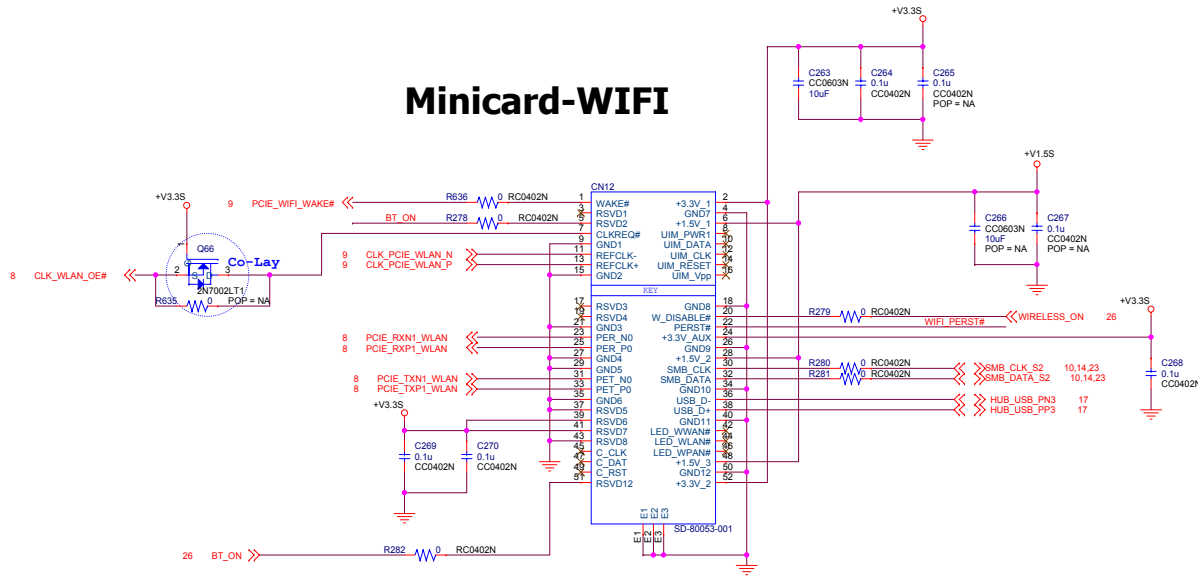


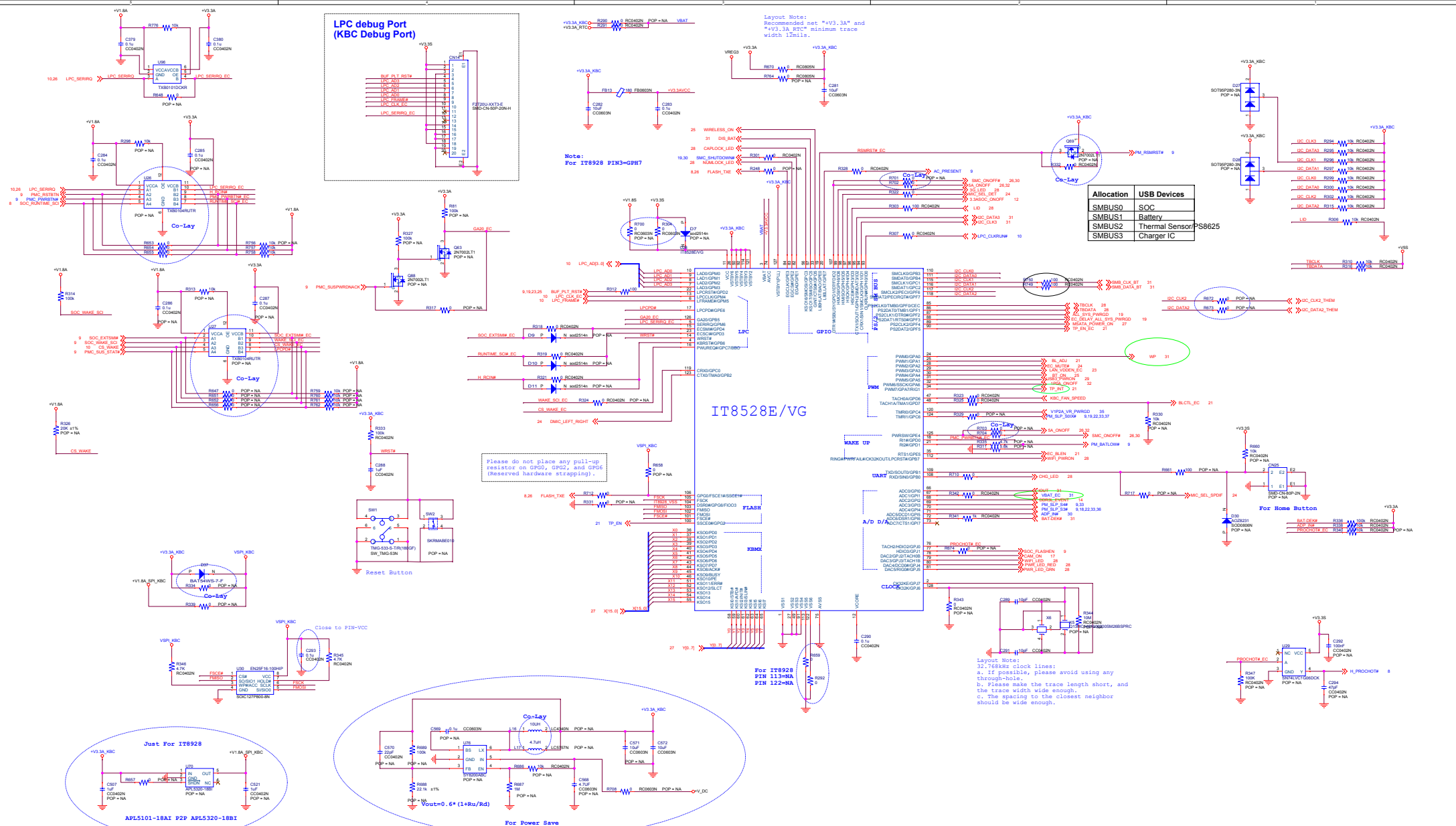




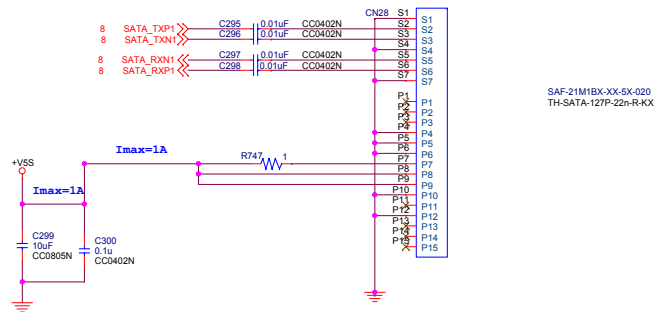


## Minicard-WIFI

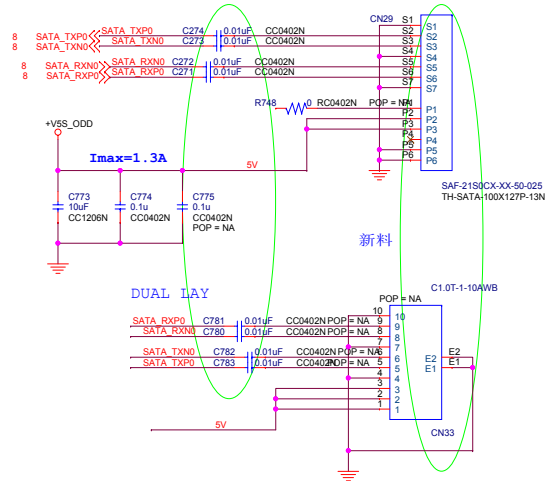




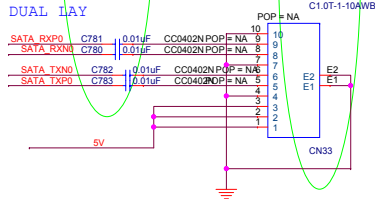
## HDD CONN



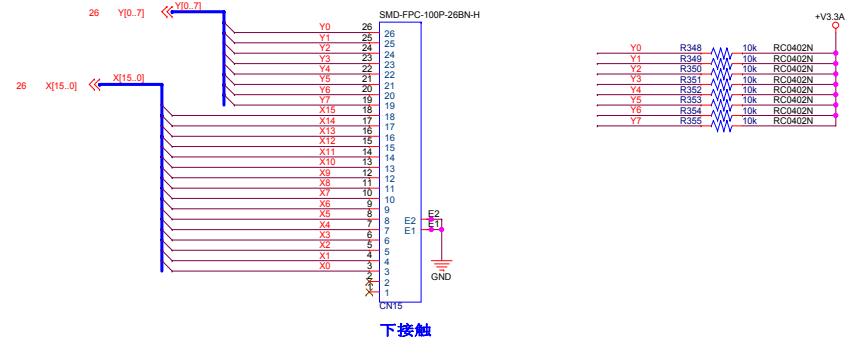
## ODD CONN



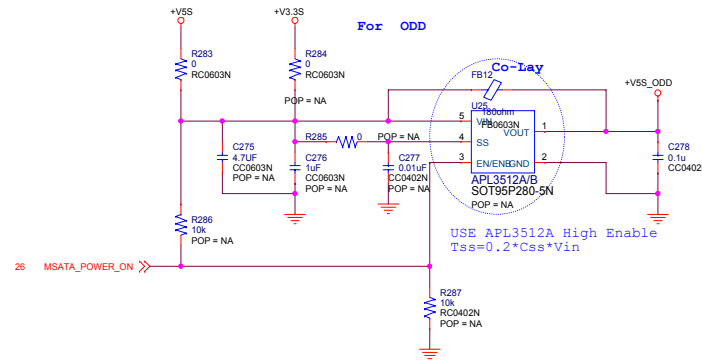
### DUAL LAY



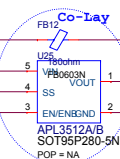
## Keyboard Connector



### 下接触

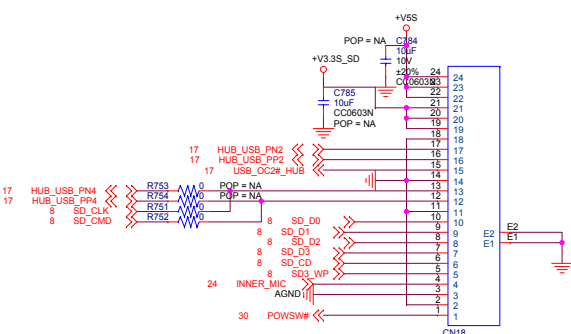


### For ODD

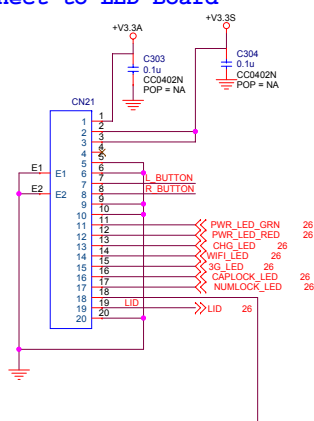


USE APL3512A High Enable  
Tss=0.2\*Css\*Vin

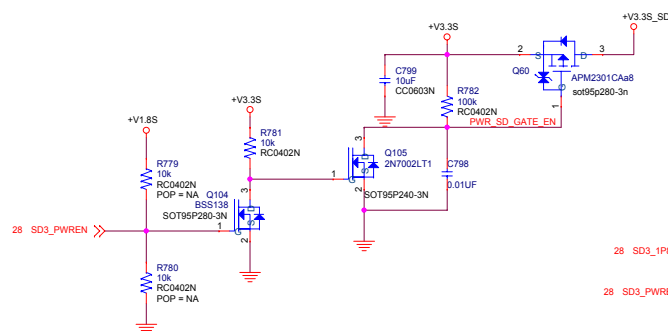
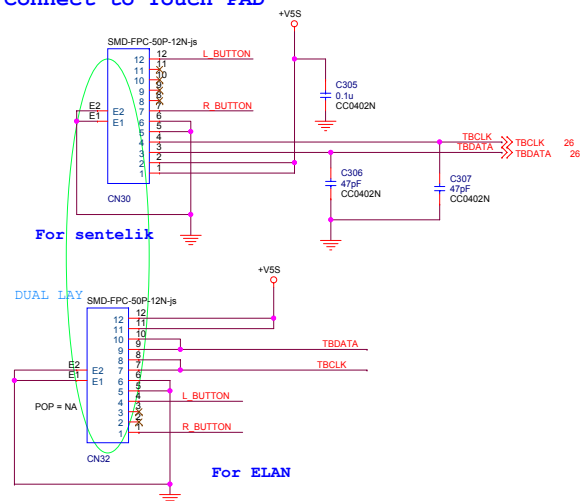
TO USB BOARD



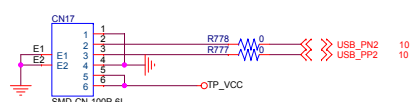
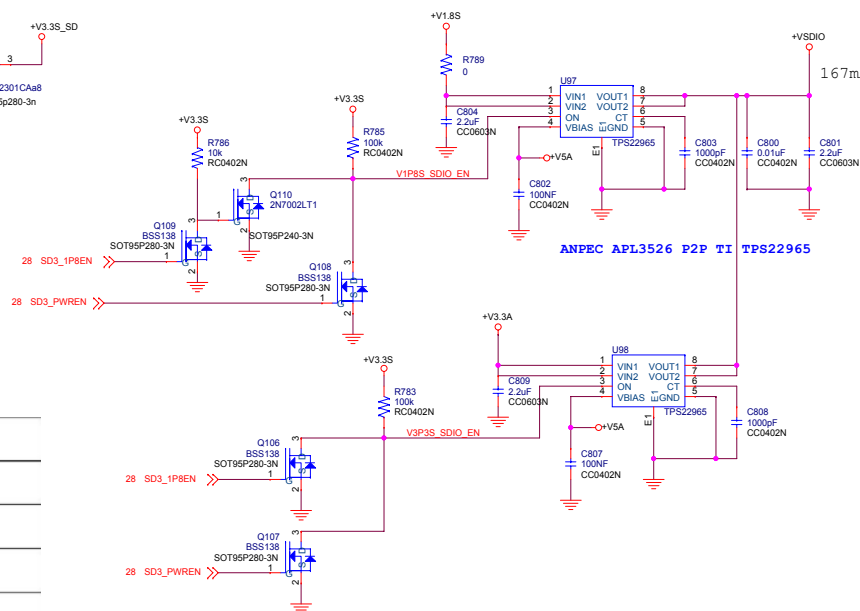
## Connect to LED Board



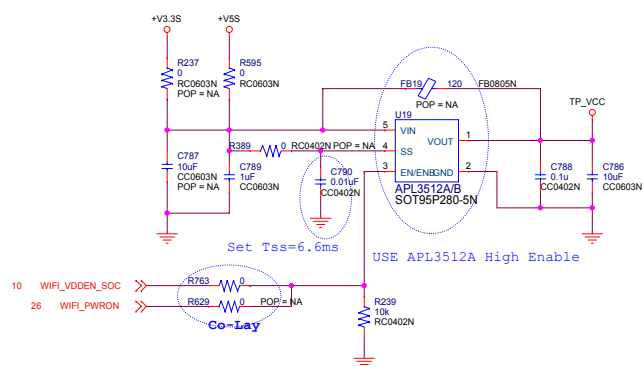
## Connect to Touch PAD

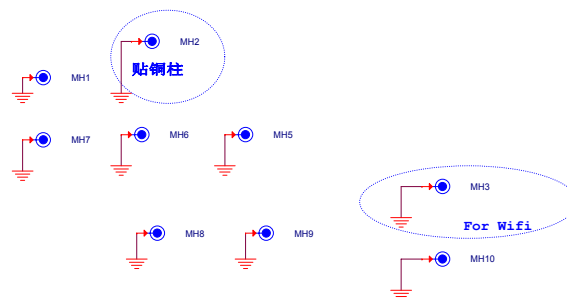
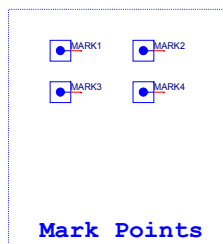
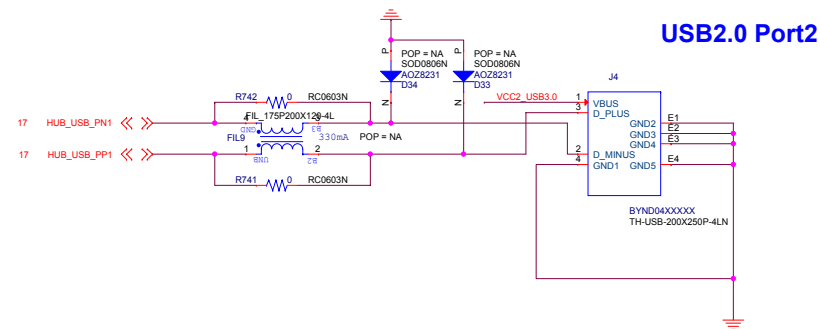
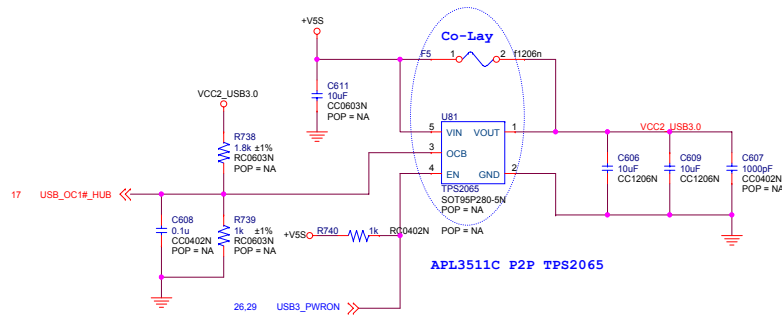
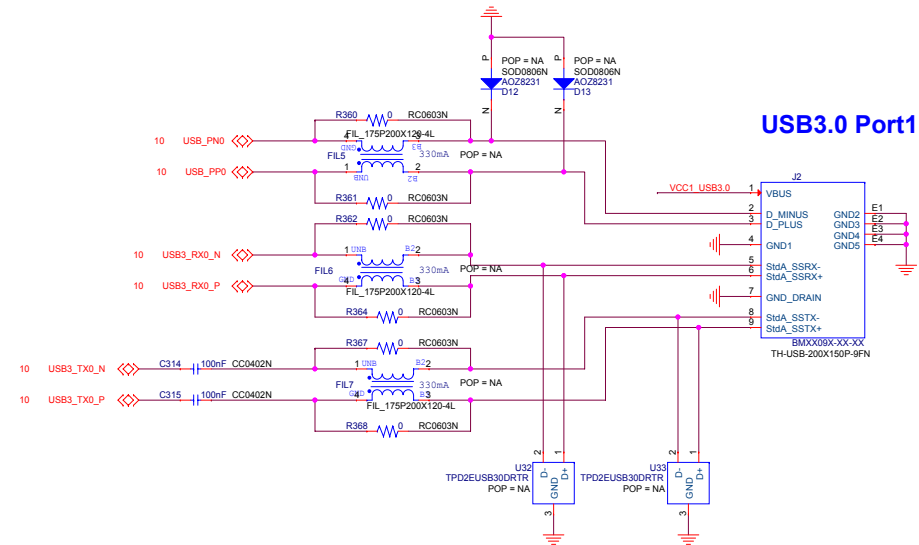
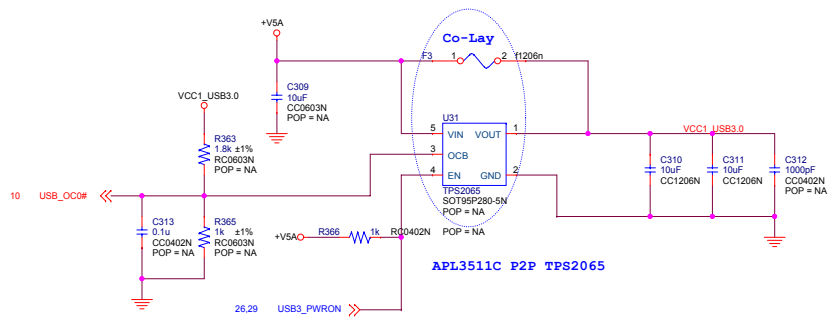


SDMMC3_PWR_EN_B	SDMMC3_1P8_EN	VSDIO (V)
1	0	0
1	1	0
0	0	3.3
0	1	1.8

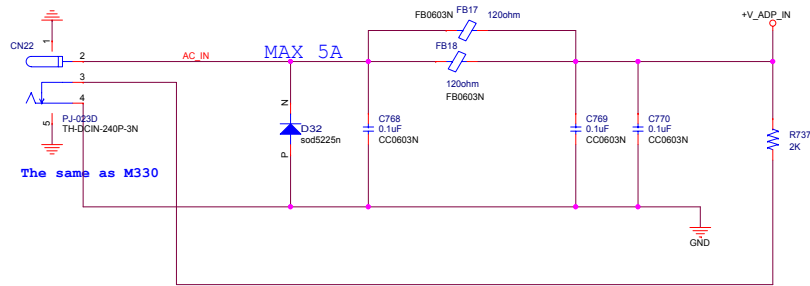


FOR TV CARD





# ADP\_IN

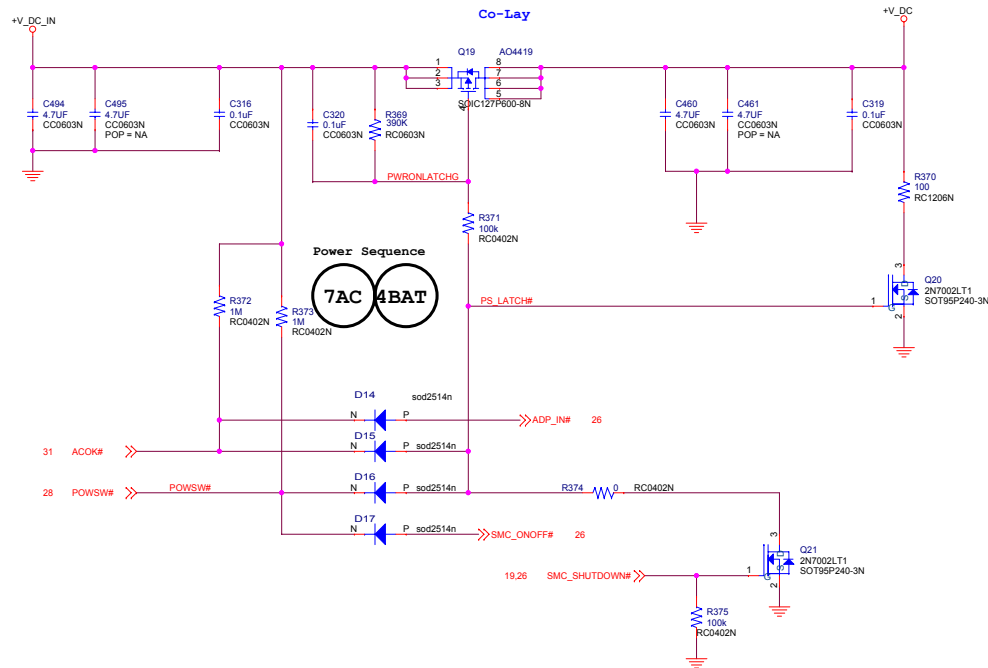


## Power Sequence

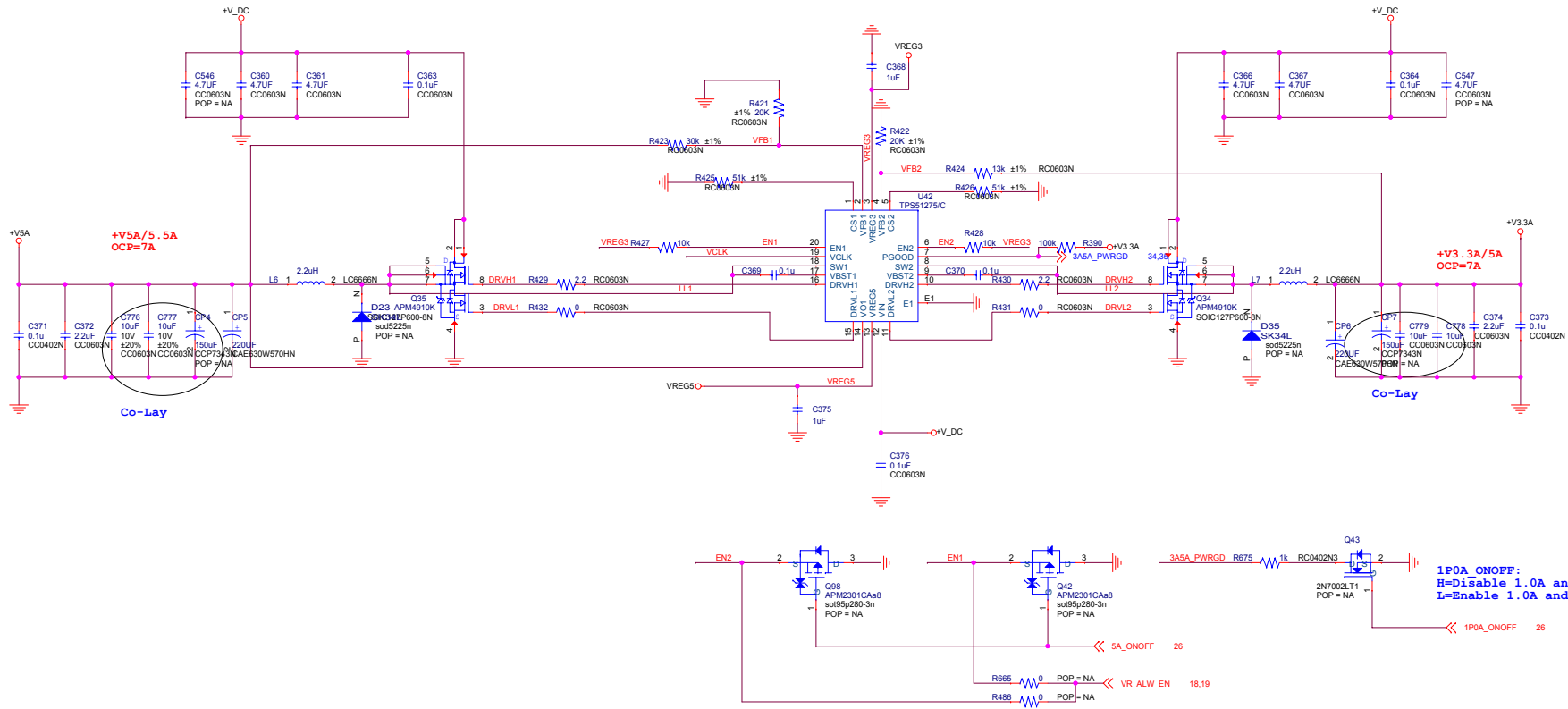
05

# Power Button Detect & Latch

Co-Lay

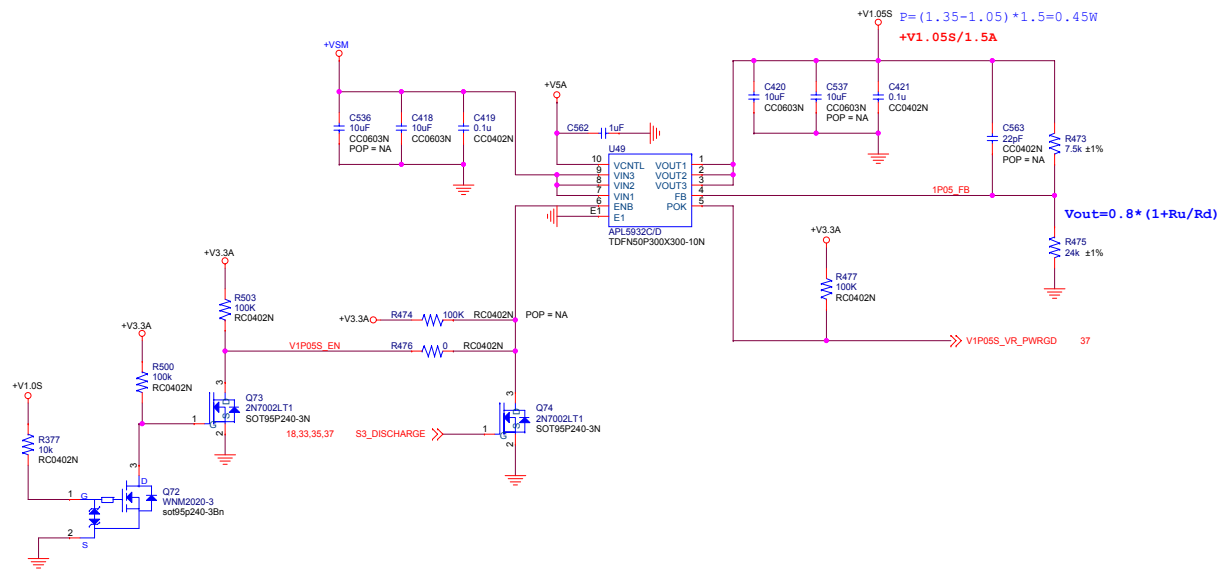
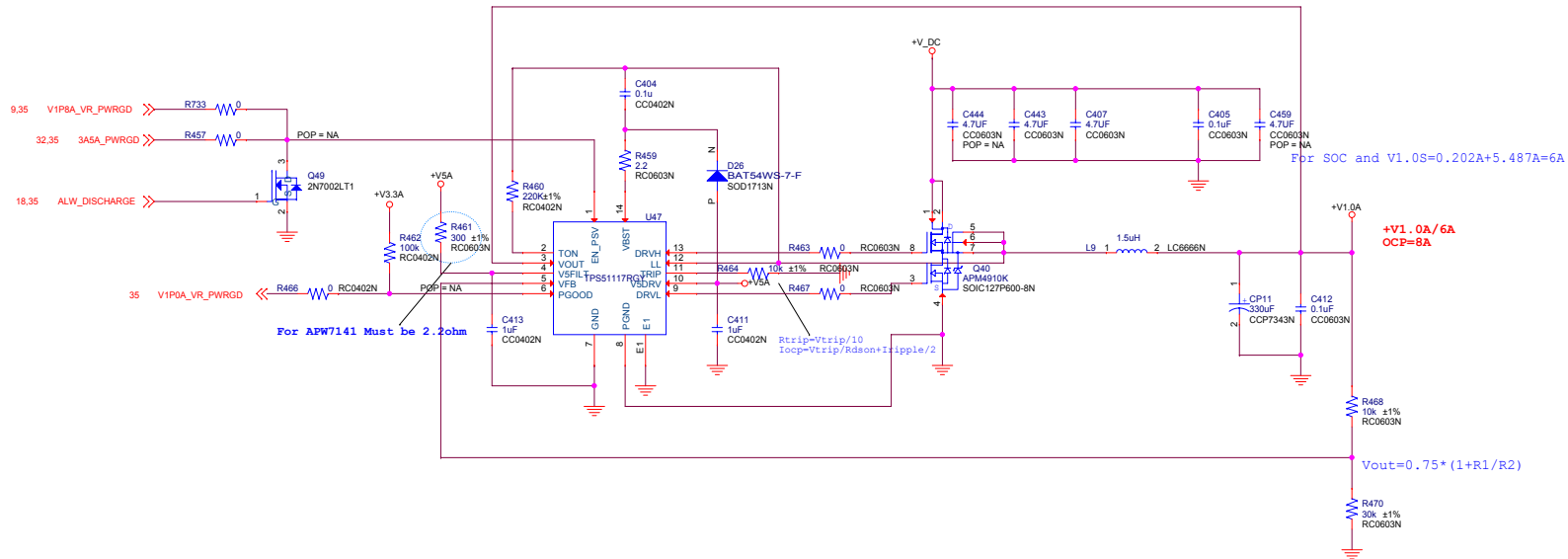


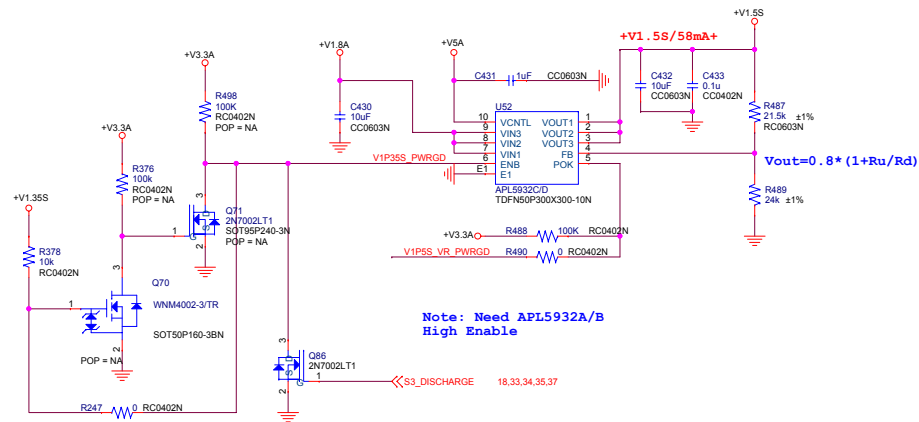
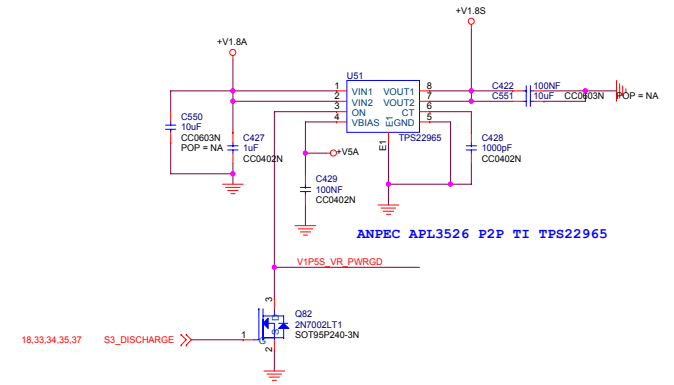
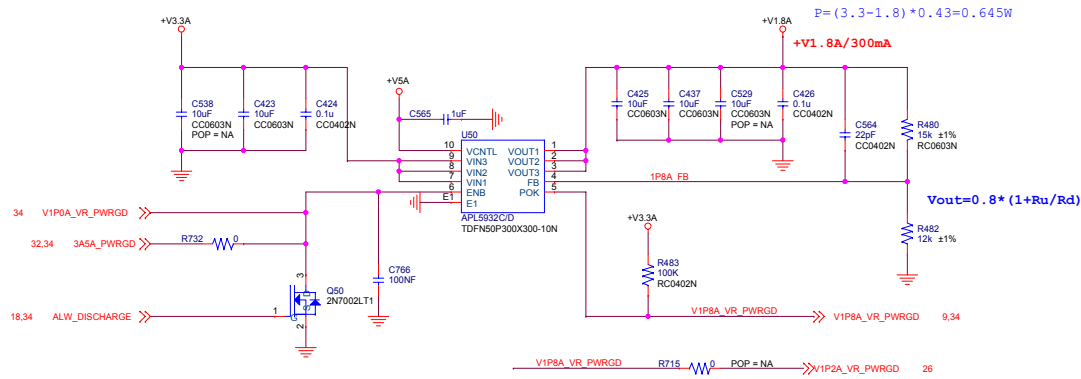






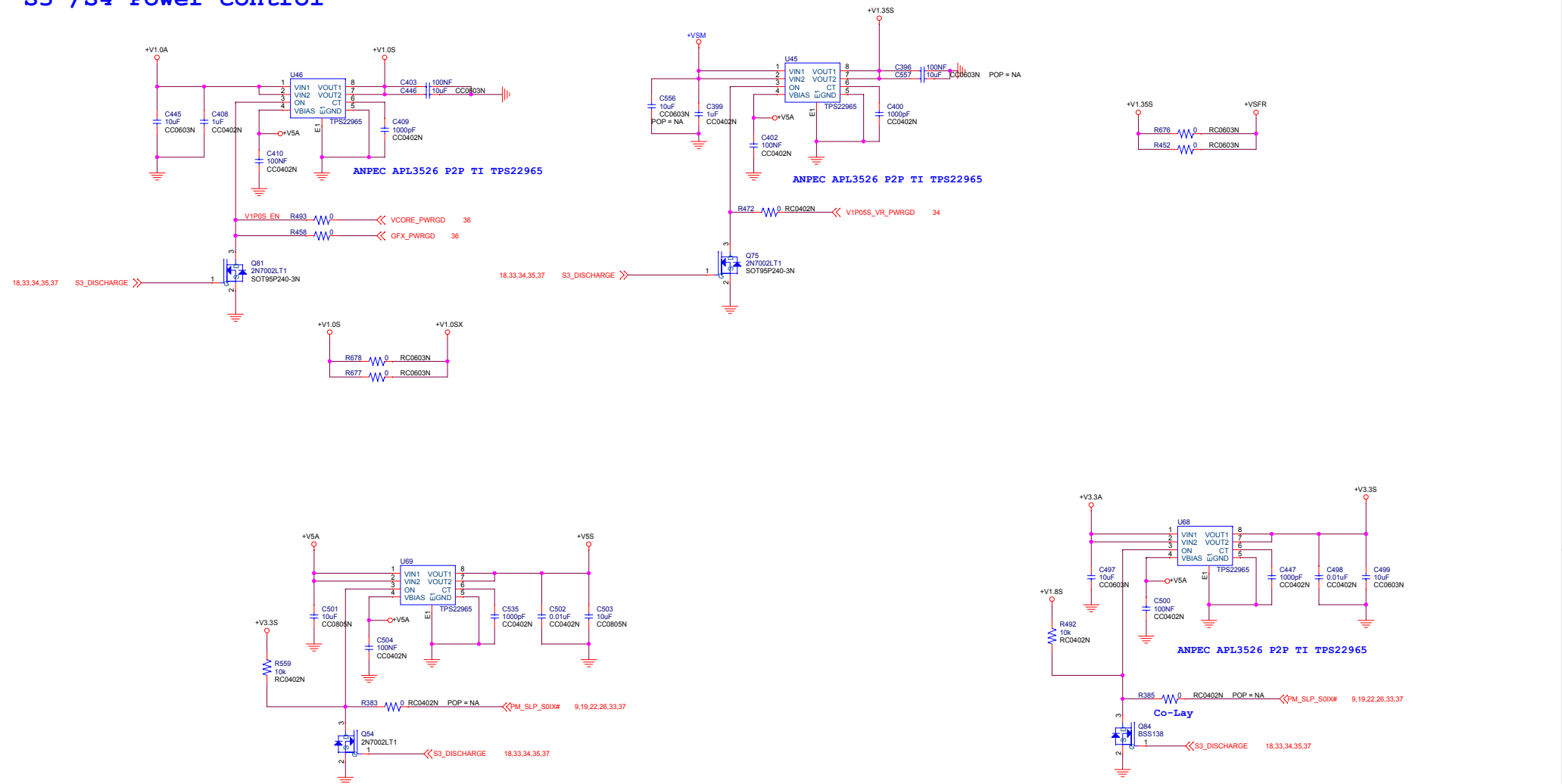


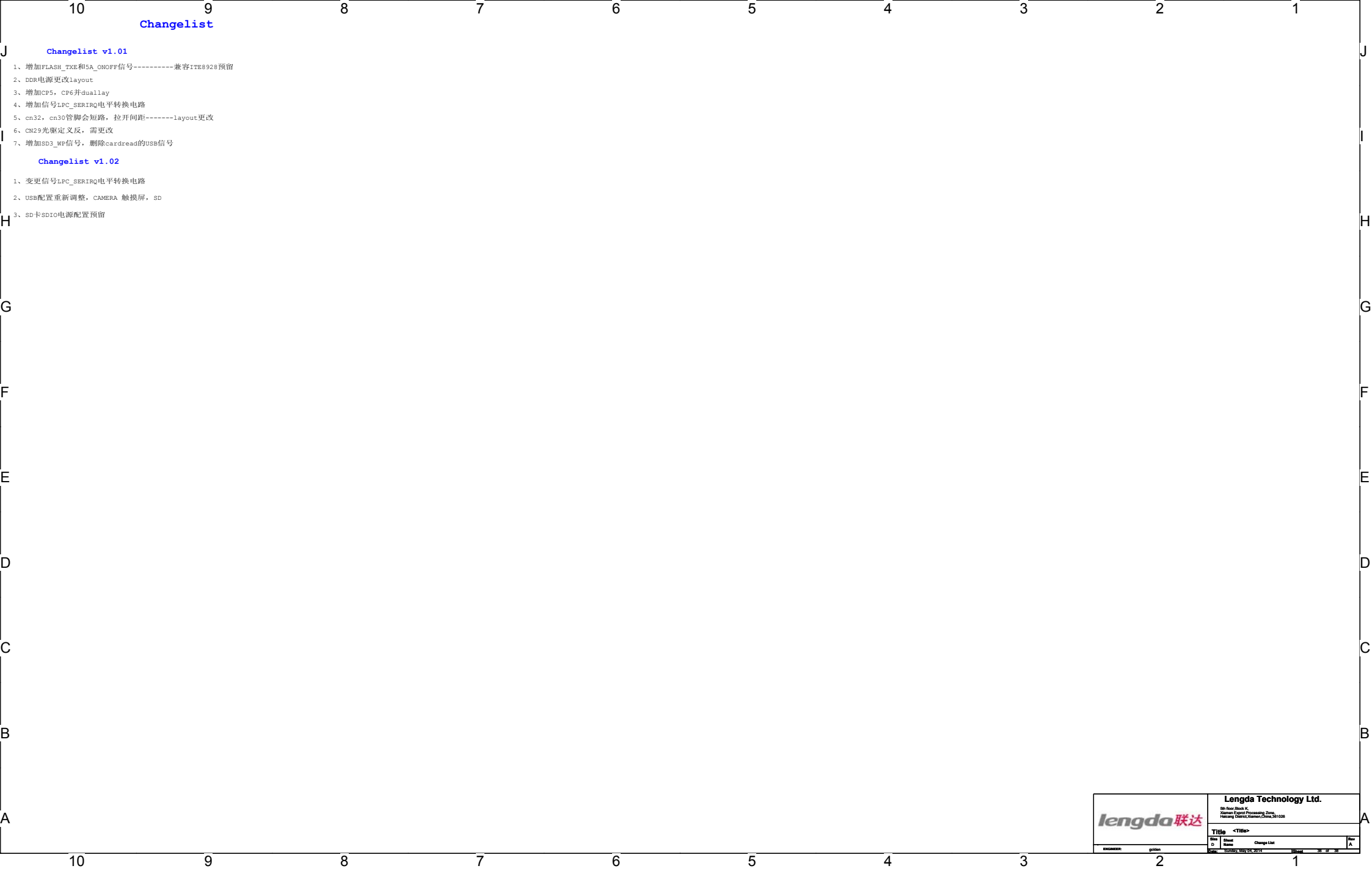






S3 /S4 Power control





Changelist

Changelist v1.01

- 1、增加FLASH\_TXE和SA\_ONOFF信号-----兼容ITE8928预留
- 2、DDR电源更改layout
- 3、增加CP5，CP6并duallay
- 4、增加信号LPC\_SERIRQ电平转换电路
- 5、cn32，cn30管脚会短路，拉开间距-----layout更改
- 6、CN29光驱定义反，需更改
- 7、增加SD3\_WF信号，删除cardread的USB信号

Changelist v1.02

- 1、变更信号LPC\_SERIRQ电平转换电路
- 2、USB配置重新调整，CAMERA 触摸屏，SD
- 3、SD卡SDIO电源配置预留